

Specification Details:

Specification: MIL-PRF-31032
 Title: Printed Circuit Board/Printed Wiring Board
 Federal Supply Class (FSC): 5998
 Conventional: No
 Specification contains quality assurance program: Yes
 MIL-STD-790 Established Reliability & High Reliability: No
 MIL-STD-690 Failure Rate Sampling Plans & Procedures: No
 Weibull Graded: No
 Specification contains space level reliability requirements: No
 Specification allows test optimization: Yes

Contact Information:

DSCC Office of Primary Involvement: Electronic Devices Team, DSCC-VQE
 Primary DSCC-VQ Contact: 614-692-0627, e-mail: vqe.ls@dla.mil
 Secondary DSCC-VQ Contact: 614-692-0631, e-mail: vqe.bw@dla.mil

Notes:

If a manufacturer desires to have test data considered for qualification, it must be certified and meet all qualification test requirements of MIL-PRF-31032 and the applicable associated specification.

The listing of printed board manufacturing lines in the QML applies only to printed boards produced in the plant(s) specified herein. Therefore, only those printed boards that have been manufactured and tested on the certified/qualified lines listed herein can be supplied as QML printed boards.

DSCC contacts for QML companies can be located in the file 31032 main points-of-contact₂ at website:
[http://www.dsccl.dla.mil/offices/sourcing and qualification/offices.asp?section=VQE](http://www.dsccl.dla.mil/offices/sourcing%20and%20qualification/offices.asp?section=VQE)

QML is a definition of a manufacturer's verified capabilities. Manufacturers may use the add-on qualification process to qualify capabilities that are not currently listed on the QML. The user is encouraged to contact the manufacturer or DSCC to make arrangements for QML availability.

The following abbreviations are used in this listing:

Ag: Silver
 Au: Gold
 CAGE: Commercial and Government Entity (Code)
 Cu: Copper
 ENIG: Electroless Nickel Immersion Gold
 HASL: Hot Air Solder Level
 ImmAg: Immersion Silver
 IR: Infrared
 LPI: Liquid Photoimageable
 MIX: Mix of SMT and THM
 Ni: Nickel
 OSP: Organic Surface Protection
 Pb: Lead
 Pd: Palladium
 PTH: Plated Thru Hole
 SMOBC: Solder Mask Over Bare Copper
 SMT: Surface-Mount Technology
 Sn: Tin
 THM: Through-Hole Mounting

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Accurate Circuit Engineering 3019 S. Kilson Drive Santa Ana, CA 92707, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 0MNN9 Contact: James Hofer Phone: 714-546-162 Fax: 714-433-7418 EMail: James@ace-pcb.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION **QUALIFICATION LETTERS:**

Specification:	MIL-PRF-31032/1, MIL-PRF-31032/2
Panel Size:	20" X 26"
Max./Min. Board Thickness:	.22"/Not Specified
Max./Min. Base CU Thickness:	.0056"/Not Specified
Max./Min. Through Hole Size:	.075"/.008" (after plating) .247"/Not Specified (mounting-after plating)
Aspect Ratio:	11:1 (Through Hole)
Max. Number of Layers:	24
Min. Conductor Width:	.003"
Min. Conductor Space:	.003" (+/-10%)
Part Mounting:	MIX, SM, THM
Rigid Base Material:	GF: Woven E-Glass, Epoxy Resin, Flame Resistant
Flex Base Material:	N/A
Finish System:	ENIG, HASL
Hole Preparation:	Permanganate Desmear/Etchback
Alternate Construction:	Blind Vias, Buried Vias, Foil Lamination, Sequential Lamination
Copper Plating:	Acid Copper
Solder Resist:	LPI
Controlled Impedance:	Characteristic, Differential 50, 75, 100 ohms +/-10%
Hole Fill/Via Plug:	Non-conductive Hole Fill/Via Plug
Flex Usage:	N/A
Hole Wall Conductive Coating:	Electroless Copper

VQE-06-12150
 VQE-07-12577
 VQE-09-18384

**SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY**

MANUFACTURER INFORMATION: American Standard Circuits RF Division, 475 Industrial Drive West Chicago, IL 60185, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 4AA34 Contact: Lori Ryan Phone: 603-639-5438 Fax: EMail: lori@asc-i.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION	QUALIFICATION LETTERS:
Specification: MIL-PRF-31032/1, MIL-PRF-31032/2 Panel Size: 12" X 18" Max./Min. Board Thickness: .062"/Not Specified Max./Min. Base CU Thickness: .006"/Not Specified (1/2 oz.) Max./Min. Through Hole Size: .052"/.009" (after plating) Aspect Ratio: 7:1 (Through Hole) Max. Number of Layers: 10 Min. Conductor Width: .004" Min. Conductor Space: .004" (+/-10%) Part Mounting: MIX, SMT, THM Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant Flex Base Material: N/A Finish System: HASL Hole Preparation: Permanganate Desmear Alternate Construction: N/A Copper Plating: Acid Copper Solder Resist: LPI Controlled Impedance: N/A Hole Fill/Via Plug: N/A Flex Usage: N/A Hole Wall Conductive Coating: Electroless Copper	VQE-08-015934

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Amphenol Printed Circuits 91 Northeastern Boulevard Nashua, NH 03062, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 57034 Contact: Denise Chevalier Phone: 603-879-3268 Fax: 603-879-2818 E-Mail: denise.chevalier@amphenol-tcs.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION **QUALIFICATION LETTERS:**

Specification:	MIL-PRF-31032/1, MIL-PRF-31032/2
Panel Size:	24" X 36", 30" X 36"
Max./Min. Board Thickness:	.322"/Not Specified
Max./Min. Base CU Thickness:	N/A
Max./Min. Through Hole Size:	Not Specified/.008"
Aspect Ratio:	0.5:1 (Blind Via) 11:1 (Through Hole)
Max. Number of Layers:	28
Min. Conductor Width:	.004"
Min. Conductor Space:	.004"
Part Mounting:	Compliant Pin, MIX, SMT, THM
Rigid Base Material:	GF: Woven E-Glass, Epoxy Resin, Flame Resistant GI: Glass Base, Woven, Polyimide Resin, Heat Resistant Hybrid Built GF/Hydrocarbon Ceramic Hydrocarbon Ceramic
Flex Base Material:	N/A
Finish System:	Electrolytic Hard & Soft Gold, Electrolytic Nickel, Fused SnB, Nickel
Hole Preparation:	Permanganate Desmear/Etchback, Plasma Desmear
Alternate Construction:	Blind Vias Mechanicall Drilled
Copper Plating:	Acid Copper, DC Plate, Pulse Plate
Solder Resist:	LPI, SMOBC, thermal cured Soldermask
Controlled Impedance:	120 ohms ± 10%, 50 ohms ± 10%
Hole Fill/Via Plug:	Conductive Via Fill, Non-conductive Via Fill
Flex Usage:	N/A
Hole Wall Conductive Coating:	N/A

VQE-06-10054
 VQE-09-17008
 VQE-97-0649

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Amphenol Printed Circuits 91 Northeastern Boulevard Nashua, NH 03062, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 57034 Contact: Denise Chevalier Phone: 603-879-3268 Fax: 603-879-2818 EMail: denise.chevalier@amphenol-tcs.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION	QUALIFICATION LETTERS:
Specification: MIL-PRF-31032/1, MIL-PRF-31032/2 Panel Size: 21" X 24" Max./Min. Board Thickness: .078"/Not Specified Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: ".026" Aspect Ratio: 3:1 Max. Number of Layers: 10 Min. Conductor Width: .004" Min. Conductor Space: .004" Part Mounting: Compliant Pin, MIX, SMT, THM Rigid Base Material: GM (Woven E-Glass, Triazine/Bismaleimide Modified Epoxy Resin) Flex Base Material: N/A Finish System: ENIG, Electrolytic Hard and Soft Gold, Electrolytic Nickel, Fused SnPb, HASL Hole Preparation: Plasma Desmear Alternate Construction: N/A Copper Plating: Acid Copper: DC Plate, Pulse Plate Solder Resist: N/A Controlled Impedance: N/A Hole Fill/Via Plug: N/A Flex Usage: N/A Hole Wall Conductive Coating: Electroless Copper	VQE-09-018717

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Calumet Electronics Corp. 25830 Depot Street Calumet, MI 49913-1985, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 65337 Contact: Robert Hall Phone: 906-337-1305 Fax: 906-337-5359 EMail: rhall@cec-up.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION **QUALIFICATION LETTERS:**

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2 Panel Size: 18" X 24" Max./Min. Board Thickness: .125"/Not Specified Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: .125"/.016" Aspect Ratio: 8:1 (Through Hole) Max. Number of Layers: 10 Min. Conductor Width: .006" Min. Conductor Space: .003" Part Mounting: SMT, THM Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant GI: Glass Base, Woven, Polyimide Resin, Heat Resistant Flex Base Material: N/A Finish System: Au, HASL, Ni Hole Preparation: FR4: Chemical Etchback, Non FR4: Plasma Etchback Alternate Construction: N/A Copper Plating: Electro-deposited Acid Copper Solder Resist: N/A Controlled Impedance: N/A Hole Fill/Via Plug: N/A Flex Usage: N/A Hole Wall Conductive Coating: N/A	VQE-03-4657 VQE-04-6280
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**SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY**

MANUFACTURER INFORMATION: Calumet Electronics Corp. 25830 Depot Street Calumet, MI 49913-1985, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 65337 Contact: Robert Hall Phone: 906-337-1305 Fax: 906-337-5359 E-Mail: rhall@cec-up.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION **QUALIFICATION LETTERS:**

Specification: Panel Size: Max./Min. Board Thickness: Max./Min. Base CU Thickness: Max./Min. Through Hole Size: Aspect Ratio: Max. Number of Layers: Min. Conductor Width: Min. Conductor Space: Part Mounting: Rigid Base Material: Flex Base Material: Finish System: Hole Preparation: Alternate Construction: Copper Plating: Solder Resist: Controlled Impedance: Hole Fill/Via Plug: Flex Usage: Hole Wall Conductive Coating:	MIL-PRF-31032/3, MIL-PRF-31032/4 12" X 180" .035"/Not Specified N/A .011"/Not Specified 3:1 (Through Hole) 7 .007" .007" SMT, THM N/A FR4-IPC-4101/21 Flexible Polyimide Clad IPC-4204/1 Flexible Polyimide Film PIC-4202/1 Flexible Polyimide Film/Acrylic IPC-4203/1 HASL Plasma Desmear/Etchback N/A Acid Copper N/A N/A N/A N/A N/A
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VQE-04-5354

**SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY**

MANUFACTURER INFORMATION: Cirex International 791 Nuttman Street Santa Clara, CA 95054,	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 4MEG7 Contact: Don Angulo Phone: 408-988-3980 Fax: 408-988-4534 EMail: dangulo@cirexintl.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION	QUALIFICATION LETTERS:
Specification: MIL-PRF-31032/2 Panel Size: 12" X 18" Max./Min. Board Thickness: .1"/Not Specified Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: Not Specified/.01" Aspect Ratio: 10:1 (Through Hole) Max. Number of Layers: 2 Min. Conductor Width: .004" Min. Conductor Space: .004" Part Mounting: MIX, SMT, THM Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant Flex Base Material: N/A Finish System: ENIG, HASL, Ni/AU Hole Preparation: Plasma Desmear Alternate Construction: N/A Copper Plating: Acid Copper Solder Resist: LPI Controlled Impedance: N/A Hole Fill/Via Plug: N/A Flex Usage: N/A Hole Wall Conductive Coating: N/A	VQE-07-014176

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION	QUALIFICATION LETTERS:
Specification: MIL-PRF-31032/3 Panel Size: 12" X 18" Max./Min. Board Thickness: .1"/Not Specified Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: Not Specified/.01" Aspect Ratio: 10:1 (Through Hole) Max. Number of Layers: 2 Min. Conductor Width: .004" Min. Conductor Space: .004" Part Mounting: MIX, SMT, THM Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant Flex Base Material: Acrylic Adhesive Polyimide Copper-Clad Adhesiveless Polyimide Finish System: ENIG, HASL, Ni/Au Hole Preparation: Plasma Desmear Alternate Construction: N/A Copper Plating: Acid Copper Solder Resist: Kapton Covelay Controlled Impedance: N/A Hole Fill/Via Plug: N/A Flex Usage: Class A Flex-to-Install, Class B Continuous Flex Hole Wall Conductive Coating: N/A	VQE-07-014176

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Cirex International 791 Nuttman Street Santa Clara, CA 95054,	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 4MEG7 Contact: Don Angulo Phone: 408-988-3980 Fax: 408-988-4534 E-Mail: dangulo@cirexxintl.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION	QUALIFICATION LETTERS:
Specification: MIL-PRF-31032/1 Panel Size: 12" X 18" Max./Min. Board Thickness: .125"/Not Specified Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: Not Specified/.01" (Mechanical) Aspect Ratio: 12.5:1 Max. Number of Layers: 22 Min. Conductor Width: .004" Min. Conductor Space: .004" Part Mounting: MIX, SMT, THM Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant GI: Glass Base, Woven, Polyimide Resin, Heat Resistant Flex Base Material: N/A Finish System: ENIG, HASL Hole Preparation: Permanganate Desmear, Plasma Etchback Alternate Construction: N/A Copper Plating: Acid Copper Solder Resist: LPI Controlled Impedance: 100 ohms +/- 10%, 50 ohms +/- 10% Hole Fill/Via Plug: N/A Flex Usage: N/A Hole Wall Conductive Coating: N/A	VQ-08-016602

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION	QUALIFICATION LETTERS:
Specification: MIL-PRF-31032/4 Panel Size: 12" X 18" Max./Min. Board Thickness: .125"/Not Specified Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: Not Specified/.01" (Mechanical) Aspect Ratio: 10:1 Max. Number of Layers: 16 Min. Conductor Width: .004" Min. Conductor Space: .004" Part Mounting: MIX, SMT, THM Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant GI: Glass Base, Woven, Polyimide Resin, Heat Resistant Flex Base Material: Acrylic Adhesie Copper Clad Adhesiveless Polyimide Finish System: ENIG, HASL Hole Preparation: Permanganate Desmear, Plasma Etchback Alternate Construction: N/A Copper Plating: Acid Coper Solder Resist: LPI Controlled Impedance: 100 ohms +/-10%, 50 ohms +/- 10% Hole Fill/Via Plug: N/A Flex Usage: Class A Flex-to-Install Hole Wall Conductive Coating: N/A	VQ-08-016602

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Colonial Circuits, Inc. 1026 Warrenton Road Fredericksburg, VA 22406-6200, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 6T499 Contact: Mike Hill Phone: 540-753-5511, x125 Fax: 540-752-2109 EMail: quality@colonialcircuits.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification: MIL-PRF-31032/1 Panel Size: 18" X 24" Max./Min. Board Thickness: .127"/Not Specified Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: .228"/.015" Aspect Ratio: 8.5:1 (Through Hole) Max. Number of Layers: 12 Min. Conductor Width: .008" Min. Conductor Space: .005" Part Mounting: PTH, SMT Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant Flex Base Material: N/A Finish System: Tin/Lead HASL Hole Preparation: Plasma Desmear Alternate Construction: N/A Copper Plating: Electrolytic Acid Copper Solder Resist: LPI Controlled Impedance: 55 Ohms ± 10% Hole Fill/Via Plug: N/A Flex Usage: N/A Hole Wall Conductive Coating: N/A		VQE-04-6002

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification: MIL-PRF-31032/1 Panel Size: 18" X 24" Max./Min. Board Thickness: .088"/Not Specified Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: .052"/.021" Aspect Ratio: 4.2:1 (Through Hole) Max. Number of Layers: 14 Min. Conductor Width: .006" Min. Conductor Space: .005" Part Mounting: PTH, SMT Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant Flex Base Material: N/A Finish System: Tin/Lead HASL Hole Preparation: Plasma Desmear Alternate Construction: N/A Copper Plating: Electrolytic Acid Copper Solder Resist: LPI Controlled Impedance: N/A Hole Fill/Via Plug: N/A Flex Usage: N/A Hole Wall Conductive Coating: N/A		VQE-04-6002

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Colonial Circuits, Inc. 1026 Warrenton Road Fredericksburg, VA 22406-6200, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 6T499 Contact: Mike Hill Phone: 540-753-5511, x125 Fax: 540-752-2109 EMail: quality@colonialcircuits.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification: MIL-PRF-31032/4 Panel Size: 12" X 18" Max./Min. Board Thickness: .093"/Not Specified Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: .045"/.025" Aspect Ratio: 3.7:1 (Through Hole) Max. Number of Layers: 10 Min. Conductor Width: .005" Min. Conductor Space: .005" Part Mounting: PTH, SMT Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant Flex Base Material: IPC-4204/1 Acrylic Adhesive Finish System: Tin/Lead Reflow Hole Preparation: Plasma Desmear/Etchback Alternate Construction: N/A Copper Plating: Electrolytic Acid Copper Solder Resist: LPI Controlled Impedance: N/A Hole Fill/Via Plug: N/A Flex Usage: N/A Hole Wall Conductive Coating: N/A	VQE-04-6002	

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification: MIL-PRF-31032/Custom Panel Size: 12" X 18" Max./Min. Board Thickness: .083"/Not Specified Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: .045"/.02" Aspect Ratio: 4.15:1 (Through Hole) Max. Number of Layers: 4 Min. Conductor Width: .01" Min. Conductor Space: .011" Part Mounting: PTH, SMT Rigid Base Material: Rogers 4003 Flex Base Material: N/A Finish System: Tin/Lead HASL Hole Preparation: Plasma Desmear Alternate Construction: N/A Copper Plating: Electrolytic Acid Copper Solder Resist: LPI Controlled Impedance: N/A Hole Fill/Via Plug: N/A Flex Usage: N/A Hole Wall Conductive Coating: N/A	VQE-04-6002	

**SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY**

<p>MANUFACTURER INFORMATION: Colonial Circuits, Inc. 1026 Warrenton Road Fredericksburg, VA 22406-6200, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 6T499 Contact: Mike Hill Phone: 540-753-5511, x125 Fax: 540-752-2109 EMail: quality@colonialcircuits.com</p>
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
<p>Specification: MIL-PRF-31032/Custom Panel Size: 12" X 18" Max./Min. Board Thickness: .031"/Not Specified Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: .117"/.02" Aspect Ratio: 1.55:1 (Through Hole) Max. Number of Layers: 2 Min. Conductor Width: .025" Min. Conductor Space: .01" Part Mounting: SMT Rigid Base Material: PTFE Resin with Ceramic Filler With or Without Woven E-Glass Flex Base Material: N/A Finish System: Tin/Lead HASL Hole Preparation: Plasma Desmear Alternate Construction: N/A Copper Plating: Electrolytic Acid Copper Solder Resist: LPI Controlled Impedance: N/A Hole Fill/Via Plug: N/A Flex Usage: N/A Hole Wall Conductive Coating: N/A</p>	<p>VQE-04-6002</p>	

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
<p>Specification: MIL-PRF-31032/1, MIL-PRF-31032/2 Panel Size: 12" X 18" Max./Min. Board Thickness: .09"/Not Specified Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: .139"/.021" Aspect Ratio: 4.29:1 (Through Hole) Max. Number of Layers: 8 Min. Conductor Width: .005" Min. Conductor Space: .005" Part Mounting: PTH, SMT Rigid Base Material: Hydrocarbon Resin with Ceramic Filler Woven E-Glass Flex Base Material: N/A Finish System: Tin/Lead HASL, Tin/Lead Reflow Hole Preparation: Plasma Desmear, Plasma Etchback Alternate Construction: N/A Copper Plating: Electrolytic Acid Copper Solder Resist: LPI Controlled Impedance: 55 ohms ±10% Hole Fill/Via Plug: N/A Flex Usage: N/A Hole Wall Conductive Coating: N/A</p>	<p>VQE-04-6002 VQE-06-010192</p>	

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Coretec Cleveland, Inc. 7 Ascot Parkway Cuyahoga Falls, OH 44223, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 7Z463 Contact: Mark Kasting Phone: 330-572-3400 Fax: 330-572-3434 EMail: mark_kasting/coretec@coretec-inc.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION **QUALIFICATION LETTERS:**

Specification:	MIL-PRF-31032/1, MIL-PRF-31032/2
Panel Size:	18" X 24"
Max./Min. Board Thickness:	.126"/Not Specified
Max./Min. Base CU Thickness:	N/A
Max./Min. Through Hole Size:	Not Specified/.014"
Aspect Ratio:	5:1 (Through Hole)
Max. Number of Layers:	16
Min. Conductor Width:	.004"
Min. Conductor Space:	.004"
Part Mounting:	SMT, THM
Rigid Base Material:	AF: Aramid Fabric, Woven, Majority Polyfunctional Epoxy Resin BI: Aramid Fabric, Nonwoven, Polyimide Resin GF: Woven E-Glass, Epoxy Resin, Flame Resistant GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
Flex Base Material:	N/A
Finish System:	Fused Tin Lead late, HASL, Selective Solder Strip-Tin Lead Plate
Hole Preparation:	Plasma Etchback
Alternate Construction:	Sequential Lamination for Blind & Buried Vias 8 layer max
Copper Plating:	Acid Copper
Solder Resist:	N/A
Controlled Impedance:	100/50 ohm ±5%
Hole Fill/Via Plug:	N/A
Flex Usage:	N/A
Hole Wall Conductive Coating:	Electroless Copper

VQE-00-0289
 VQE-01-0910
 VQE-05-008414
 VQE-06-010963

SECTION I
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MANUFACTURER INFORMATION: Coretec Cleveland, Inc. 7 Ascot Parkway Cuyahoga Falls, OH 44223, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 7Z463 Contact: Mark Kasting Phone: 330-572-3400 Fax: 330-572-3434 EMail: mark_kasting/coretec@coretec-inc.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION	QUALIFICATION LETTERS:
Specification: MIL-PRF-31032/3, MIL-PRF-31032/4 Panel Size: 18" X 24" Max./Min. Board Thickness: .126"/Not Specified Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: Not Specified/.017" Aspect Ratio: 10:1 (Through Hole) Max. Number of Layers: 11 Min. Conductor Width: .003" Min. Conductor Space: .003" Part Mounting: SMT, THM Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant GI: Glass Base, Woven, Polyimide Resin, Heat Resistant Flex Base Material: IPC-4204/1 Acrylic Adhesive IPC-4204/11 Adhesiveless Finish System: HASL Hole Preparation: Plasma Etchback Alternate Construction: N/A Copper Plating: Acid Copper Solder Resist: N/A Controlled Impedance: N/A Hole Fill/Via Plug: N/A Flex Usage: Class A Flex to Install Hole Wall Conductive Coating: Electroless Copper	VQE-01-0909 VQE-06-010963

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Coretec Denver, Inc. 10570 Bradford Road Littleton, CO 80127, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 75815 Contact: Douglas N. Berry Phone: 303-904-6119 Fax: 303-933-2934 EMail: dberry@coretec-denver.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION **QUALIFICATION LETTERS:**

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2 Panel Size: 18" X 24" Max./Min. Board Thickness: .125"/Not Specified Max./Min. Base CU Thickness: .001"/Not Specified Max./Min. Through Hole Size: .109"/.013" Aspect Ratio: 7:1 Max. Number of Layers: 20 Min. Conductor Width: .004" Min. Conductor Space: .004" Part Mounting: MIX, SMT, THM Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant Flex Base Material: N/A Finish System: ENIG, HASL, IR Reflow Following SnPb Plate Hole Preparation: Plasma Desmear/Etchback Alternate Construction: N/A Copper Plating: Acid Copper Solder Resist: LPI Controlled Impedance: N/A Hole Fill/Via Plug: Non-conductive Epoxy Hole Fill/Via Plug Flex Usage: N/A Hole Wall Conductive Coating: Electroless Copper	VQE-02-0317 VQE-05-7627 VQE-05-9014 VQE-09-18719
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**SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY**

MANUFACTURER INFORMATION: Coretec Denver, Inc. 10570 Bradford Road Littleton, CO 80127, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 75815 Contact: Douglas N. Berry Phone: 303-904-6119 Fax: 303-933-2934 EMail: dberry@coretec-denver.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION	QUALIFICATION LETTERS:
Specification: MIL-PRF-31032/1, MIL-PRF-31032/2 Panel Size: 18" X 24" Max./Min. Board Thickness: .125"/Not Specified Max./Min. Base CU Thickness: .001"/" Max./Min. Through Hole Size: .109"/.013" Aspect Ratio: 10:1 Max. Number of Layers: 20 Min. Conductor Width: .004" Min. Conductor Space: .004" Part Mounting: MIX, SMT, THM Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant Flex Base Material: N/A Finish System: ENIG, HASL, IR Reflow following SnPb plate Hole Preparation: Plasma Desmear/Etchback Alternate Construction: N/A Copper Plating: Acid Copper Solder Resist: LPI Controlled Impedance: N/A Hole Fill/Via Plug: Non-conductive Epoxy Hole Fill/Via Plug Flex Usage: N/A Hole Wall Conductive Coating: Electroless Copper	VQE-02-0217 VQE-05-7626 VQE-05-9014 VQE-09-18719

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Coretec Denver, Inc. 10570 Bradford Road Littleton, CO 80127, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 75815 Contact: Douglas N. Berry Phone: 303-904-6119 Fax: 303-933-2934 EMail: dberry@coretec-denver.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification:	MIL-PRF-31032/1, MIL-PRF-31032/2	VQE-02-0317 VQE-05-7627 VQE-05-9014 VQE-09-18719
Panel Size:	18" X 24"	
Max./Min. Board Thickness:	.092"/Not Specified	
Max./Min. Base CU Thickness:	.001"/"	
Max./Min. Through Hole Size:	.053"/.039"	
Aspect Ratio:	3:1	
Max. Number of Layers:	12	
Min. Conductor Width:	.004"	
Min. Conductor Space:	.004"	
Part Mounting:	MIX, SMT, THM	
Rigid Base Material:	GM: Glass Base, Woven, Triazine and/or Bismaleimide Modified Epoxy Resin, Flame Resistant	
Flex Base Material:	N/A	
Finish System:	ENIG, HASL, IR Reflow following SnPb plate	
Hole Preparation:	Plasma Desmear/Etchback	
Alternate Construction:	N/A	
Copper Plating:	Acid Copper	
Solder Resist:	LPI	
Controlled Impedance:	N/A	
Hole Fill/Via Plug:	Non-conductive Epoxy Hole Fill/Via Plug	
Flex Usage:	N/A	
Hole Wall Conductive Coating:	Electroless Copper	

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Coretec, Inc. 8150 Sheppard Avenue East Scarborough, Ontario, Canada M1B 5K2	PLANT LOCATIONS: 1. Same Address as Manufacturer 2. Coretec, Inc., CAGE Code: 3AF82, 2020 Ellesmere Road, Scarborough, Ontario, Canada M1H 2Z8	CAGE Code: 3AF82 Contact: Noor Al-Shaikh Phone: 416-208-2100 Fax: 416-439-1582 EMail: alshaikh@coretec-inc.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification:	MIL-PRF-31032/1, MIL-PRF-31032/2	VQE-04-006240
Panel Size:	18" X 24"	VQE-08-015407
Max./Min. Board Thickness:	.08"/Not Specified	
Max./Min. Base CU Thickness:	N/A	
Max./Min. Through Hole Size:	Not Specified/.01" (as drilled)	
Aspect Ratio:	7:1 (Through Hole)	
Max. Number of Layers:	14	
Min. Conductor Width:	.005"	
Min. Conductor Space:	.005"	
Part Mounting:	MIX, SMT, THM	
Rigid Base Material:	GF: Woven E-Glass, Epoxy Resin, Flame Resistant	
Flex Base Material:	N/A	
Finish System:	ENIG, HASL	
Hole Preparation:	Chemical desmear	
Alternate Construction:	N/A	
Copper Plating:	Acid Copper	
Solder Resist:	LPI	
Controlled Impedance:	Characteristics \pm 10%, Differential \pm 10%	
Hole Fill/Via Plug:	Non-conductive Via Plug	
Flex Usage:	N/A	
Hole Wall Conductive Coating:	Electroless Copper	

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification:	MIL-PRF-31032/1, MIL-PRF-31032/2	VQE-04-006240
Panel Size:	18" X 24"	VQE-08-015407
Max./Min. Board Thickness:	.08"/Not Specified	
Max./Min. Base CU Thickness:	N/A	
Max./Min. Through Hole Size:	Not Specified/.01" (as drilled)	
Aspect Ratio:	7:1 (Through Hole)	
Max. Number of Layers:	14	
Min. Conductor Width:	.005"	
Min. Conductor Space:	.005"	
Part Mounting:	MIX, SMT, THM	
Rigid Base Material:	GI: Glass Base, Woven, Polyimide Resin, Heat Resistant	
Flex Base Material:	N/A	
Finish System:	ENIG, HASL	
Hole Preparation:	Desmear, Plasma Etchback	
Alternate Construction:	N/A	
Copper Plating:	Acid Copper	
Solder Resist:	LPI	
Controlled Impedance:	Characteristics +/-10%, Differential +/-10%	
Hole Fill/Via Plug:	Non-conductive Via Plug	
Flex Usage:	N/A	
Hole Wall Conductive Coating:	Electroless Copper	

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Cosmotronic, Inc. 16721 Noyes Avenue Irvine, CA 92606, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 63695 Contact: Alan Exley Phone: 949-660-0740 Fax: 949-553-8371 E-Mail: alan_exley@cosmotronic.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION **QUALIFICATION LETTERS:**

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2	VQE-04-006966
	VQE-05-009107
	VQE-06-010085
	VQE-06-011248
Panel Size: 18" X 24"	
Max./Min. Board Thickness: .335"/Not Specified	
Max./Min. Base CU Thickness: N/A	
Max./Min. Through Hole Size: Not Specified/.014"	
Aspect Ratio: 15:1 (Through Hole)	
Max. Number of Layers: 36	
Min. Conductor Width: .005"	
Min. Conductor Space: .004"	
Part Mounting: MIX, SMT, THM	
Rigid Base Material: AF: Aramid Fabric, Woven, Majority Polyfunctional Epoxy Resin BF: Aramid Fabric, Nonwoven, Epoxy Resin BI: Aramid Fabric, Nonwoven, Polyimide Resin GF: Woven E-Glass, Epoxy Resin, Flame Resistant GI: Glass Base, Woven, Polyimide Resin, Heat Resistant GM: Glass Base, Woven, Triazine and/or Bismaleimide Modified Epoxy Resin, Flame Resistant	
Flex Base Material: N/A	
Finish System: ENIG, Fused SnPB, HASL, Selective Solder Strip-Tin Lead Plate	
Hole Preparation: Plasma Desmear/Etchback	
Alternate Construction: Blind Vias, Sequential Lamination	
Copper Plating: Electro-deposited Acid Copper	
Solder Resist: LPI, SMOBC	
Controlled Impedance: 50 ohms ± 10% nominal/tolerance	
Hole Fill/Via Plug: N/A	
Flex Usage: N/A	
Hole Wall Conductive Coating: N/A	

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Cosmotronic, Inc. 16721 Noyes Avenue Irvine, CA 92606, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 63695 Contact: Alan Exley Phone: 949-660-0740 Fax: 949-553-8371 E-Mail: alan_exley@cosmotronic.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION **QUALIFICATION LETTERS:**

Specification:	MIL-PRF-31032/3, MIL-PRF-31032/4
Panel Size:	18" X 24"
Max./Min. Board Thickness:	.165"/Not Specified
Max./Min. Base CU Thickness:	N/A
Max./Min. Through Hole Size:	Not Specified/.012"
Aspect Ratio:	8:1 (Through Hole)
Max. Number of Layers:	22
Min. Conductor Width:	.006"
Min. Conductor Space:	.008"
Part Mounting:	SMT, THM
Rigid Base Material:	GF: Woven E-Glass, Epoxy Resin, Flame Resistant GI: Glass Base, Woven, Polyimide Resin, Heat Resistant GI/GM Composite Material GM: Glass Base, Woven, Triazine and/or Bismaleimide Modified Epoxy Resin, Flame Resistant
Flex Base Material:	IPC-4204/1 Acrylic Adhesive IPC-4204/11 Adhesiveless
Finish System:	ENIG, Fused SnPB, HASL, Selective Solder Strip-Tin Lead Plate,
Hole Preparation:	N/A
Alternate Construction:	N/A
Copper Plating:	Electro-deposited Acid Copper
Solder Resist:	LPI, SMOBC
Controlled Impedance:	N/A
Hole Fill/Via Plug:	N/A
Flex Usage:	Class A Flex to Install, Class B Continuous Flex
Hole Wall Conductive Coating:	N/A

VQE-04-006966
 VQE-05-009107
 VQE-06-010085

**SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY**

MANUFACTURER INFORMATION: Cosmotronic, Inc. 16721 Noyes Avenue Irvine, CA 92606, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 63695 Contact: Alan Exley Phone: 949-660-0740 Fax: 949-553-8371 EMail: alan_exley@cosmotronic.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION **QUALIFICATION LETTERS:**

Specification: MIL-PRF-31032/Custom Panel Size: 12" X 18" Max./Min. Board Thickness: .225"/Not Specified Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: Not Specified/.02" Aspect Ratio: 10:1 (Through Hole) Max. Number of Layers: 16 Min. Conductor Width: .011" Min. Conductor Space: .007" Part Mounting: SMT Rigid Base Material: Rogers 4003 Ceramic-Filled Thermoset Resin Rogers 4003/GI Composite Flex Base Material: N/A Finish System: ENIG, HASL Hole Preparation: Plasma Desmear/Etchback Alternate Construction: Blind Vias, Sequential Lamination Copper Plating: Electro-deposited Acid Copper Solder Resist: LPI, SMOBC Controlled Impedance: N/A Hole Fill/Via Plug: N/A Flex Usage: N/A Hole Wall Conductive Coating: N/A	VQE-04-006966 VQE-05-009107 VQE-06-010085
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SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

<p>MANUFACTURER INFORMATION: Diversified Systems 3939 West 56th Street Indianapolis, IN 46254, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 5S706 Contact: Linda Bell Phone: 317-299-9547, x238 Fax: 317-298-2061 EMail: linda.bell@divsys.com</p>
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification:	MIL-PRF-31032/1, MIL-PRF-31032/2	VQE-01-0309
Panel Size:	18" X 24"	VQE-02-0015
Max./Min. Board Thickness:	.11"/Not Specified	
Max./Min. Base CU Thickness:	N/A	
Max./Min. Through Hole Size:	".012"	
Aspect Ratio:	5.5:1 (Through Hole)	
Max. Number of Layers:	14	
Min. Conductor Width:	.005"	
Min. Conductor Space:	.005"	
Part Mounting:	SMT, THM	
Rigid Base Material:	GF: Woven E-Glass, Epoxy Resin, Flame Resistant GI: Glass Base, Woven, Polyimide Resin, Heat Resistant	
Flex Base Material:	N/A	
Finish System:	HASL	
Hole Preparation:	Permanganate Desmear/Etchback	
Alternate Construction:	Foil Lamination	
Copper Plating:	Electro-deposited Acid Copper	
Solder Resist:	Dry Film, LPI	
Controlled Impedance:	Embedded Stripline & Microstrip	
Hole Fill/Via Plug:	N/A	
Flex Usage:	N/A	
Hole Wall Conductive Coating:	Electroless Copper	

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Dynaco Corp. 1000 South Priest Drive Tempe, AZ 85281-5238, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 61642 Contact: Ted Edwards Phone: 480-736-3728 Fax: 480-921-9830 EMail: tedwards@dynacocorp.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification:	MIL-PRF-31032/1, MIL-PRF-31032/2	VQE-05-9356
Panel Size:	18" X 24"	
Max./Min. Board Thickness:	.1"/Not Specified	
Max./Min. Base CU Thickness:	.001"/Not Specified	
Max./Min. Through Hole Size:	.045"/.032"	
Aspect Ratio:	3:1 (Through Hole)	
Max. Number of Layers:	10	
Min. Conductor Width:	.01"	
Min. Conductor Space:	.01"	
Part Mounting:	THM	
Rigid Base Material:	GF: Woven E-Glass, Epoxy Resin, Flame Resistant GI: Glass Base, Woven, Polyimide Resin, Heat Resistant	
Flex Base Material:	N/A	
Finish System:	HASL	
Hole Preparation:	Permanganate Desmear/Etchback	
Alternate Construction:	N/A	
Copper Plating:	Acid Copper	
Solder Resist:	N/A	
Controlled Impedance:	N/A	
Hole Fill/Via Plug:	N/A	
Flex Usage:	N/A	
Hole Wall Conductive Coating:	N/A	

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification:	MIL-PRF-31032/3, MIL-PRF-31032/4	VQE-05-9356 VQE-06-10600
Panel Size:	12" X 18", 18" X 24"	
Max./Min. Board Thickness:	.12"/Not Specified	
Max./Min. Base CU Thickness:	.001"/Not Specified	
Max./Min. Through Hole Size:	.045"/.01"	
Aspect Ratio:	12:1 (Through Hole)	
Max. Number of Layers:	20	
Min. Conductor Width:	.004"	
Min. Conductor Space:	.006"	
Part Mounting:	THM	
Rigid Base Material:	GI: Glass Base, Woven, Polyimide Resin, Heat Resistant	
Flex Base Material:	IPC-4204/1 Acrylic Adhesive	
Finish System:	Fused Sn/Pb, HASL	
Hole Preparation:	Permanganate Desmear/Etchback, Plasma Etchback	
Alternate Construction:	N/A	
Copper Plating:	Electroless Acid Copper, Electroplated Acid Copper	
Solder Resist:	N/A	
Controlled Impedance:	N/A	
Hole Fill/Via Plug:	N/A	
Flex Usage:	N/A	
Hole Wall Conductive Coating:	N/A	

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Dynaco Corp. 1000 South Priest Drive Tempe, AZ 85281-5238, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 61642 Contact: Ted Edwards Phone: 480-736-3728 Fax: 480-921-9830 EMail: tedwards@dynacocorp.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION	QUALIFICATION LETTERS:
Specification: MIL-PRF-31032/3, MIL-PRF-31032/4 Panel Size: 12" X 18", 18" X 24" Max./Min. Board Thickness: .1"/Not Specified Max./Min. Base CU Thickness: .001"/Not Specified Max./Min. Through Hole Size: .045"/.032" Aspect Ratio: 3:1 (Through Hole) Max. Number of Layers: 10 Min. Conductor Width: .01" Min. Conductor Space: .01" Part Mounting: THM Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant Flex Base Material: IPC-241/11 Adhesiveless IPC-4204/11 Adhesiveless Finish System: HASL Hole Preparation: Permanganate Desmear/Etchback Alternate Construction: Foil Lamination Copper Plating: Acid Copper Solder Resist: N/A Controlled Impedance: N/A Hole Fill/Via Plug: N/A Flex Usage: Class A Flex to Install, Class B Continuous Flex Hole Wall Conductive Coating: N/A	VQE-05-9356

**SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY**

MANUFACTURER INFORMATION: Dynamic & Proto Circuits, Inc. 869 Barton Street Stoney Creek, Ontario, Canada L8E 5G6	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 38898 Contact: Stephen Hazell Phone: 905-643-9900 Fax: 905-643-9911 EMail: stephenhazell@dapc.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION **QUALIFICATION LETTERS:**

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2 Panel Size: 16" X 18" Max./Min. Board Thickness: .125"/Not Specified Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: .039"/.018" (0.0135" Drilled) Aspect Ratio: 9.3:1 (Through Hole) Max. Number of Layers: 16 Min. Conductor Width: .005" Min. Conductor Space: .005" Part Mounting: MIX, SMT, THM Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant GI: Glass Base, Woven, Polyimide Resin, Heat Resistant Flex Base Material: N/A Finish System: HASL Hole Preparation: Plasma Etchback Alternate Construction: N/A Copper Plating: Acid Copper Solder Resist: Dry Film Solder Resist Plugs, LPI Controlled Impedance: N/A Hole Fill/Via Plug: N/A Flex Usage: N/A Hole Wall Conductive Coating: N/A	VQE-00-0007 VQE-01-0311 VQE-03-0818 VQE-98-1143
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SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Dynamic Details, Inc. 1200 Severn Way Dulles, VA 20166-8904, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 0K703 Contact: Tony Trnka Phone: 703-652-2266 Fax: 703-652-2271 EMail: atnka@va.ddiglobal.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION	QUALIFICATION LETTERS:
Specification: MIL-PRF-31032/1, MIL-PRF-31032/2 Panel Size: 18" X 24" Max./Min. Board Thickness: .1"/Not Specified Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: .05"/.009" (nominal) .15"/Not Specified (non-PTH) Aspect Ratio: 10:1 Max. Number of Layers: 22 Min. Conductor Width: .004" Min. Conductor Space: .003" Part Mounting: BGA, MIX, SMT, THM Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant GI: Glass Base, Woven, Polyimide Resin, Heat Resistant Flex Base Material: N/A Finish System: ENIG, HASL Hole Preparation: Plasma Desmear/Etchback Alternate Construction: 0.005 Blind Vias laser, 0.006 Blind Micro Vias laser, Buried Resistors 33 ohms ± 15% Copper Plating: Electrolytic Acid Copper Solder Resist: LPI Controlled Impedance: Differential 100 ohms ± 10%, Single Ended 50 ohms ± 10% Hole Fill/Via Plug: Buried Vias with Non-conductive Via Fill Flex Usage: N/A Hole Wall Conductive Coating: Electroless Copper	VQE-03-3545

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Dynamic Details, Inc., Anaheim 1220 N. Simon Circle Anaheim, CA 92806, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 0BSG1 Contact: Rick Sylvain Phone: 714-688-7371 Fax: EMail: rsylvain@ddiglobal.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification: Panel Size: Max./Min. Board Thickness: Max./Min. Base CU Thickness: Max./Min. Through Hole Size: Aspect Ratio: Max. Number of Layers: Min. Conductor Width: Min. Conductor Space: Part Mounting: Rigid Base Material: Flex Base Material: Finish System: Hole Preparation: Alternate Construction: Copper Plating: Solder Resist: Controlled Impedance: Hole Fill/Via Plug: Flex Usage: Hole Wall Conductive Coating:	MIL-PRF-31032/1, MIL-PRF-31032/2 18" X 24" .115"/Not Specified N/A .009"/Not Specified (Vias) ".05" (Plated Hole Size) 10:1 22 .004" .006" BGA, MIX, SMT, THM GF: Woven E-Glass, Epoxy Resin, Flame Resistant N/A ENIG, HASL Plasma Desmear, Plasma Etchback Foil Lamination Electrodeposited Acid Copper, Electroless Acid Copper LPI Differential: 100 ohms +/-10%, Single Ended: 50 ohms +/-10% Blind Vias, Buried Vias with Non-conductive Fill N/A N/A	VQ-09-018147

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification: Panel Size: Max./Min. Board Thickness: Max./Min. Base CU Thickness: Max./Min. Through Hole Size: Aspect Ratio: Max. Number of Layers: Min. Conductor Width: Min. Conductor Space: Part Mounting: Rigid Base Material: Flex Base Material: Finish System: Hole Preparation: Alternate Construction: Copper Plating: Solder Resist: Controlled Impedance: Hole Fill/Via Plug: Flex Usage: Hole Wall Conductive Coating:	MIL-PRF-31032/1, MIL-PRF-31032/2 N/A .1"/Not Specified N/A .045"/.032" (drilled) 3:1 10 .01" .01" THM GI: Glass Base, Woven, Polyimide Resin, Heat Resistant N/A HASL ENIG Plasma Desmear, Plasma Etchback Foil Lamination Electrodeposited Acid Copper, Electroless Acid Copper LPI N/A , N/A N/A	VQ-09-018147

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Electro Plate Circuitry 1430 Century Drive Carrollton, TX 75006, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 79616 Contact: James McNeal Phone: 972-466-0818 Fax: 972-466-9078 EMail: jjimm@eplate.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification:	MIL-PRF-31032/1, MIL-PRF-31032/2	VQE-06-010333
		VQE-06-011433
Panel Size:	18" X 24", 18" X 16"	
Max./Min. Board Thickness:	.12"/.03"	
Max./Min. Base CU Thickness:	N/A	
Max./Min. Through Hole Size:	".008"	
Aspect Ratio:	9.3:1 (Through Hole)	
Max. Number of Layers:	14	
Min. Conductor Width:	.004"	
Min. Conductor Space:	.004"	
Part Mounting:	MIX, SMT, THM	
Rigid Base Material:	GF: Woven E-Glass, Epoxy Resin, Flame Resistant	
	GI: Glass Base, Woven, Polyimide Resin, Heat Resistant	
Flex Base Material:	N/A	
Finish System:	ENIG, HASL, Hard Gold, Reflowed SnPb	
Hole Preparation:	Plasma Desmear/Etchback	
Alternate Construction:	Blind/Buried Vias, Filled Vias, Foil Lamination, Sequential Lamination	
Copper Plating:	Acid Copper	
Solder Resist:	Dry Film, LPI	
Controlled Impedance:	± 3% Tolerance	
Hole Fill/Via Plug:	CB100 conductive, UVP100 non-conductive	
Flex Usage:	N/A	
Hole Wall Conductive Coating:	Electroless	

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Electrotek Corp. 7745 S. 10th Street Oak Creek, WI 53154, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 66030 Contact: Tom Tikusis Phone: 414-762-1390 Fax: 414-762-1510 EMail: sales@boards4u.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION **QUALIFICATION LETTERS:**

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2 Panel Size: 18" X 24" Max./Min. Board Thickness: .115"/Not Specified Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: ".012" Aspect Ratio: 9:1 (Through Hole) Max. Number of Layers: 18 Min. Conductor Width: .003" Min. Conductor Space: .003" Part Mounting: MIX, SMT, THM Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant GI: Glass Base, Woven, Polyimide Resin, Heat Resistant Flex Base Material: N/A Finish System: ENIG, Electrolytic Nickel/Gold, HASL, ImmAg Hole Preparation: Permanganate Desmear, Plasma Etchback Alternate Construction: Cap Lamination, Foil Lamination Copper Plating: Electroplated Acid Copper Solder Resist: Dry Film, LPI Controlled Impedance: GF: 100 ohms/50 ohms ± 10%, GI: 100 ohms ± 10% Hole Fill/Via Plug: Via-fill Technology, 0.016" ±25% Diameter Flex Usage: N/A Hole Wall Conductive Coating: Electroless Copper	VQ-06-011451 VQ-08-014513 VQE-09-018692
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SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Endicott Interconnect Technologies, Inc. 1701 North Street P.O. Box 658, Endicott, NY 13760, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 3ECL3 Contact: Jose Rios Phone: 607-755-5896 Fax: 607-755-4649 EMail: JoseA.Rios@eitny.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION **QUALIFICATION LETTERS:**

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2 Panel Size: 24" X 28" Max./Min. Board Thickness: .116"/Not Specified Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: ".01" Aspect Ratio: 12:1 (Through Hole) Max. Number of Layers: 30 Min. Conductor Width: .003" Min. Conductor Space: .004" Part Mounting: MIX, SMT, THM Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant Flex Base Material: N/A Finish System: ENIG, HASL Hole Preparation: Glass Etch, Permanganate Desmear, Plasma Etchback Alternate Construction: Cap-Lamination, Foil-Lamination Copper Plating: Electroplated Acid Copper Solder Resist: LPI Controlled Impedance: N/A Hole Fill/Via Plug: N/A Flex Usage: N/A Hole Wall Conductive Coating: N/A	VQE-04-005311 VQE-07-012236 VQE-07-013506 VQE-08-015922
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SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Endicott Interconnect Technologies, Inc. 1701 North Street P.O. Box 658, Endicott, NY 13760, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 3ECL3 Contact: Jose Rios Phone: 607-755-5896 Fax: 607-755-4649 EMail: JoseA.Rios@eitny.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification:	MIL-PRF-31032/1, MIL-PRF-31032/2	VQE-04-005311 VQE-07-012236 VQE-07-013506
Panel Size:	18" X 24"	
Max./Min. Board Thickness:	.084"/Not Specified	
Max./Min. Base CU Thickness:	N/A	
Max./Min. Through Hole Size:	Not Specified/.012"	
Aspect Ratio:	7:1 (Through Hole)	
Max. Number of Layers:	12	
Min. Conductor Width:	.004"	
Min. Conductor Space:	.004"	
Part Mounting:	MIX, SMT, THM	
Rigid Base Material:	GI: Glass Base, Woven, Polyimide Resin, Heat Resistant	
Flex Base Material:	N/A	
Finish System:	ENIG, HASL	
Hole Preparation:	Pemanganate Desmear, Plasma Etchback	
Alternate Construction:	Cap-Lamination, Foil-Lamination	
Copper Plating:	Electroplated Acid Copper	
Solder Resist:	LPI	
Controlled Impedance:	N/A	
Hole Fill/Via Plug:	N/A	
Flex Usage:	N/A	
Hole Wall Conductive Coating:	N/A	

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification:	MIL-PRF-31032/Custom	VQE-04-005311 VQE-07-012236 VQE-07-013506
Panel Size:	19.5" X 24"	
Max./Min. Board Thickness:	.153"/Not Specified	
Max./Min. Base CU Thickness:	N/A	
Max./Min. Through Hole Size:	Not Specified/.02"	
Aspect Ratio:	7.6:1 (Through Hole)	
Max. Number of Layers:	19	
Min. Conductor Width:	.005"	
Min. Conductor Space:	.005"	
Part Mounting:	MIX	
Rigid Base Material:	GI: Glass Base, Woven, Polyimide Resin, Heat Resistant	
Flex Base Material:	N/A	
Finish System:	ENIG	
Hole Preparation:	Pemanganate Desmear, Plasma Etchback	
Alternate Construction:	Foil-Lamination, Copper Core	
Copper Plating:	Electroplated Acid Copper	
Solder Resist:	LPI	
Controlled Impedance:	N/A	
Hole Fill/Via Plug:	N/A	
Flex Usage:	N/A	
Hole Wall Conductive Coating:	N/A	

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Firan Technology Group 250 Finchdene Square Scarborough, Ontario, Canada M1X 1A5	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: L2665 Contact: Bryan Clark Phone: 416-299-4000 Fax: 416-292-4308 E-Mail: byanclark@firantechnology.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION **QUALIFICATION LETTERS:**

Specification:	MIL-PRF-31032/1, MIL-PRF-31032/2
Panel Size:	18" X 24"
Max./Min. Board Thickness:	.22"/Not Specified
Max./Min. Base CU Thickness:	N/A
Max./Min. Through Hole Size:	Not Specified/.005" (Laser Control Depth) Not Specified/.006" (Buried Via Mechanical Drill) .025"/.008" (Mechanical Drill)
Aspect Ratio:	7:1 (Through Hole)
Max. Number of Layers:	20
Min. Conductor Width:	.004"
Min. Conductor Space:	.004"
Part Mounting:	MIX, SMT, THM
Rigid Base Material:	BI: Aramid Fabric, Nonwoven, Polyimide Resin GF: Woven E-Glass, Epoxy Resin, Flame Resistant GI: Glass Base, Woven, Polyimide Resin, Heat Resistant GM: Glass Base, Woven, Triazine and/or Bismaleimide Modified Epoxy Resin, Flame Resistant GX: Glass Base, Woven, Polytetrafluoroethylene Resin, Flame Resistant
Flex Base Material:	N/A
Finish System:	ENIG, HASL, Immersion Tin, Silver, Reflow Solder
Hole Preparation:	Permanganate Desmear, Plasma Etchback
Alternate Construction:	Sequential Lamination for Blind & Buried Vias and Micro Vias
Copper Plating:	Electroless Acid Copper, Electrolytic Acid Copper
Solder Resist:	Hole Fill, LPI
Controlled Impedance:	Characteristic \pm 10%, Differential \pm 10%
Hole Fill/Via Plug:	N/A
Flex Usage:	N/A
Hole Wall Conductive Coating:	N/A

VQE-05-009339
 VQE-06-010764
 VQE-06-010889

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Global Innovation Corp. 901 Hensley Drive Wylie, TX 75098, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 04RV5 Contact: Bob Noland Phone: 214-291-1427 Fax: EMail: bnoland@globalinnovationcorp.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION	QUALIFICATION LETTERS:
Specification: MIL-PRF-31032/6 Panel Size: 9" X 16" Max./Min. Board Thickness: .036"/Not Specified Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: Not Specified/.031" Aspect Ratio: 1.2:1 (Through Hole) Max. Number of Layers: 2 Min. Conductor Width: .005" Min. Conductor Space: .005" Part Mounting: MIX Rigid Base Material: GR: Glass Base, Nonwoven, Polytetrafluoroethylene Resin, Flame Resistant Flex Base Material: N/A Finish System: HASL Hole Preparation: Fluoroetch Alternate Construction: N/A Copper Plating: Electro-deposited Acid Copper Solder Resist: LPI Controlled Impedance: N/A Hole Fill/Via Plug: N/A Flex Usage: N/A Hole Wall Conductive Coating: Electroless Copper	VQE-07-13270 VQE-09-17797

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Global Innovation Corp. 901 Hensley Drive Wylie, TX 75098, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 04RV5 Contact: Bob Noland Phone: 214-291-1427 Fax: EMail: bnoland@globalinnovationcorp.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION **QUALIFICATION LETTERS:**

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2 Panel Size: 18" X 24" Max./Min. Board Thickness: .119"/Not Specified Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: Not Specified/.01" Aspect Ratio: 7.5:1 (Through Hole) Max. Number of Layers: 18 Min. Conductor Width: .004" Min. Conductor Space: .005" Part Mounting: MIX Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant Flex Base Material: N/A Finish System: HASL Hole Preparation: Permanganate Desmear, Plasma Etchback Alternate Construction: Foil Lamination Copper Plating: Electro-deposited Acid Copper Solder Resist: Dry Film, LPI Controlled Impedance: N/A Hole Fill/Via Plug: N/A Flex Usage: N/A Hole Wall Conductive Coating: Electroless Copper	VQE-03-4341 VQE-04-5599 VQE-04-5891 VQE-05-7288
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SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Global Innovation Corp. 901 Hensley Drive Wylie, TX 75098, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 04RV5 Contact: Bob Noland Phone: 214-291-1427 Fax: EMail: bnoland@globalinnovationcorp.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification:	MIL-PRF-31032/1, MIL-PRF-31032/2	VQE-04-4957
Panel Size:	18" X 24"	VQE-05-7288
Max./Min. Board Thickness:	.074"/Not Specified	
Max./Min. Base CU Thickness:	N/A	
Max./Min. Through Hole Size:	Not Specified/.012"	
Aspect Ratio:	6.2:1 (Through Hole)	
Max. Number of Layers:	12	
Min. Conductor Width:	.005"	
Min. Conductor Space:	.005"	
Part Mounting:	MIX	
Rigid Base Material:	GI: Glass Base, Woven, Polyimide Resin, Heat Resistant	
Flex Base Material:	N/A	
Finish System:	HASL	
Hole Preparation:	Plasma Etchback	
Alternate Construction:	N/A	
Copper Plating:	Electro-deposited Acid Copper	
Solder Resist:	LPI	
Controlled Impedance:	62/37.5 ohms ±10%	
Hole Fill/Via Plug:	N/A	
Flex Usage:	N/A	
Hole Wall Conductive Coating:	Electroless Copper	

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Hamby Corporation 27704 Avenue Scott Valencia, CA 91355, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 07284 Contact: Sue Sharp Phone: 661-257-1924 Fax: 661-257-1213 E-Mail: suesharp@hambycorp.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification: MIL-PRF-31032/1, MIL-PRF-31032/2 Panel Size: 12" X 18" Max./Min. Board Thickness: .035"/Not Specified Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: .05"/.02" (drilled) Aspect Ratio: 2:1 (Through Hole) Max. Number of Layers: 6 Min. Conductor Width: .009" Min. Conductor Space: .009" Part Mounting: MIX, SMT, THM Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant GI: Glass Base, Woven, Polyimide Resin, Heat Resistant Flex Base Material: N/A Finish System: HASL, Ni/Au Hole Preparation: Plasma Etchback/Desmear Alternate Construction: N/A Copper Plating: Electrodeposited Acid Copper Solder Resist: N/A Controlled Impedance: N/A Hole Fill/Via Plug: N/A Flex Usage: N/A Hole Wall Conductive Coating: Electroless Copper	VQE-09-017349	

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification: MIL-PRF-31032/3, MIL-PRF-31032/4 Panel Size: 18" X 24" Max./Min. Board Thickness: .085"/Not Specified Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: .035"/.018" Aspect Ratio: 5:1 (Through Hole) Max. Number of Layers: 11 Min. Conductor Width: .004" Min. Conductor Space: .004" Part Mounting: MIX, SMT, THM Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant Flex Base Material: IPC-4204/1 Acrylic Adhesive IPC-4204/11 Adhesiveless Finish System: HASL, Ni/Au Hole Preparation: Plasma Etchback/Desmear Alternate Construction: N/A Copper Plating: Electrodeposited Acid Copper Solder Resist: N/A Controlled Impedance: Characteristic: 35-50 ohms +/-10%, Differential: 100 ohms +/-10% Hole Fill/Via Plug: N/A Flex Usage: N/A Hole Wall Conductive Coating: Electroless Copper	VQE-08-014596	

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Hans Brockstedt GmbH Leiterplattenschnelldienst, Clara-Immerwahr-Str. 7 24145, Kiel, Germany	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: C4831 Contact: Hilmar Klammer Phone: 0049-431-71966-0, -30 Fax: 0049-431-71966-29 E-Mail: klammer@brockstedt.de
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION **QUALIFICATION LETTERS:**

Specification:	MIL-PRF-31032/1, MIL-PRF-31032/2
Panel Size:	9" X 13", 13" X 20", 15" X 21", 18" X 24"
Max./Min. Board Thickness:	.2"/Not Specified
Max./Min. Base CU Thickness:	N/A
Max./Min. Through Hole Size:	Not Specified/.004" (Laser Drilled) Not Specified/.01" (Mech. Drilled)
Aspect Ratio:	1:1 (Blind Vias) 7:1 (Through Hole)
Max. Number of Layers:	12
Min. Conductor Width:	.004"
Min. Conductor Space:	.004"
Part Mounting:	MIX, SMT, THM
Rigid Base Material:	GF: Woven E-Glass, Epoxy Resin, Flame Resistant Gl: Glass Base, Woven, Polyimide Resin, Heat Resistant
Flex Base Material:	N/A
Finish System:	Electroless Nickel/Gold, Electroless Sn, Electroplated Nickel/Gold, Electroplated SnPb, Fused SnPb, HASL
Hole Preparation:	Plasma Desmear/Etchback
Alternate Construction:	Blind Vias, Buried Vias, Laser Drilled Vias
Copper Plating:	Acid Copper
Solder Resist:	LPI
Controlled Impedance:	N/A
Hole Fill/Via Plug:	N/A
Flex Usage:	N/A
Hole Wall Conductive Coating:	Electroless Copper

VQE-03-2619
VQE-05-7480

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Hans Brockstedt GmbH Leiterplattenschnelldienst, Clara-Immerwahr-Str. 7 24145, Kiel, Germany	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: C4831 Contact: Hilmar Klammer Phone: 0049-431-71966-0, -30 Fax: 0049-431-71966-29 E-Mail: klammer@brockstedt.de
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION **QUALIFICATION LETTERS:**

Specification:	MIL-PRF-31032/3, MIL-PRF-31032/4
Panel Size:	9" X 13", 13" X 20"
Max./Min. Board Thickness:	.2"/Not Specified
Max./Min. Base CU Thickness:	N/A
Max./Min. Through Hole Size:	Not Specified/.004" (Laser Drilled) Not Specified/.01" (Mech. Drilled)
Aspect Ratio:	1:1 (Blind Vias) 7:1 (Through Hole)
Max. Number of Layers:	12
Min. Conductor Width:	.004"
Min. Conductor Space:	.004"
Part Mounting:	MIX, SMT, THM
Rigid Base Material:	GF: Woven E-Glass, Epoxy Resin, Flame Resistant GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
Flex Base Material:	IPC-4204/1 Acrylic Adhesive IPC-4204/11 Adhesiveless
Finish System:	Electroless Nickel/Gold, Electroless Sn, Electroplated Nickel/Gold, Electroplated SnPb, Fused SnPb, HASL
Hole Preparation:	Plasma Desmear/Etchback
Alternate Construction:	Blind Vias, Buried Vias, Laser Drilled Vias
Copper Plating:	Acid Copper
Solder Resist:	LPI
Controlled Impedance:	N/A
Hole Fill/Via Plug:	N/A
Flex Usage:	Class A Flex to Install
Hole Wall Conductive Coating:	Electroless Copper

VQE-03-2619
 VQE-05-7480

**SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY**

MANUFACTURER INFORMATION: Hughes Circuits 540 S. Pacific Street San Marcos, CA 92078-4056, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 1KXU6 Contact: Joe Hughes Phone: 760-744-0300 Fax: 760-744-6388 EMail: joe@hughescircuits.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification:	MIL-PRF-31032/1, MIL-PRF-31032/2	VQE-07-014018
Panel Size:	18" X 24"	
Max./Min. Board Thickness:	.08"/Not Specified	
Max./Min. Base CU Thickness:	N/A	
Max./Min. Through Hole Size:	Not Specified/.01" .012"/Not Specified	
Aspect Ratio:	7:1 (Through Hole)	
Max. Number of Layers:	10	
Min. Conductor Width:	.005"	
Min. Conductor Space:	.005"	
Part Mounting:	MIX	
Rigid Base Material:	G1: Glass Base, Woven, Polyimide Resin, Heat Resistant	
Flex Base Material:	N/A	
Finish System:	HASL	
Hole Preparation:	Plasma Desmea	
Alternate Construction:	N/A	
Copper Plating:	Electrodeposited Acid Copper	
Solder Resist:	LPI	
Controlled Impedance:	N/A	
Hole Fill/Via Plug:	N/A	
Flex Usage:	N/A	
Hole Wall Conductive Coating:	N/A	

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Lockheed Martin Systems Integration-Owego 1801 State Route 17C Owego, NY 13827, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 03640 Contact: Melita Nagerl Phone: 607-751-4665 Fax: 607-751-7714 EMail: melita.nagerl@lmco.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification: Panel Size: Max./Min. Board Thickness: Max./Min. Base CU Thickness: Max./Min. Through Hole Size: Aspect Ratio: Max. Number of Layers: Min. Conductor Width: Min. Conductor Space: Part Mounting: Rigid Base Material: Flex Base Material: Finish System: Hole Preparation: Alternate Construction: Copper Plating: Solder Resist: Controlled Impedance: Hole Fill/Via Plug: Flex Usage: Hole Wall Conductive Coating:	MIL-PRF-31032/1, MIL-PRF-31032/2 18" X 24" .2"/Not Specified N/A Not Specified/.02" 8:1 (Through Hole) 16 .004" .004" SMT, THM AF: Aramid Fabric, Woven, Majority Polyfunctional Epoxy Resin N/A Fused SnPb, HASL, NiAu Permanganate Desmear, Plasma Etchback N/A Electro-deposited Acid Copper LPI N/A N/A N/A Electroless Copper	VQE-00-0961 VQE-99-0130

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification: Panel Size: Max./Min. Board Thickness: Max./Min. Base CU Thickness: Max./Min. Through Hole Size: Aspect Ratio: Max. Number of Layers: Min. Conductor Width: Min. Conductor Space: Part Mounting: Rigid Base Material: Flex Base Material: Finish System: Hole Preparation: Alternate Construction: Copper Plating: Solder Resist: Controlled Impedance: Hole Fill/Via Plug: Flex Usage: Hole Wall Conductive Coating:	MIL-PRF-31032/1, MIL-PRF-31032/2 18" X 24" .095"/Not Specified N/A Not Specified/.014" 6.8:1 (Through Hole) 14 .004" .004" SMT, THM BI: Aramid Fabric, Nonwoven, Polyimide Resin N/A Fused SnPb, HASL, NiAu Permanganate Desmear N/A Electro-deposited Acid Copper LPI N/A N/A N/A Electroless Copper	VQE-01-0539

**SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY**

MANUFACTURER INFORMATION: Lockheed Martin Systems Integration-Owego 1801 State Route 17C Owego, NY 13827, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 03640 Contact: Melita Nagerl Phone: 607-751-4665 Fax: 607-751-7714 EMail: melita.nagerl@lmco.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION **QUALIFICATION LETTERS:**

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2 Panel Size: N/A Max./Min. Board Thickness: .2"/Not Specified Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: Not Specified/.018" Aspect Ratio: 8:1 (Through Hole) Max. Number of Layers: 24 Min. Conductor Width: .004" Min. Conductor Space: .004" Part Mounting: SMT, THM Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant Flex Base Material: N/A Finish System: Fused SnPb, HASL, NiAu Hole Preparation: Permanganate Desmear, Plasma Etchback Alternate Construction: N/A Copper Plating: Electro-deposited Acid Copper Solder Resist: LPI Controlled Impedance: N/A Hole Fill/Via Plug: N/A Flex Usage: N/A Hole Wall Conductive Coating: Electroless Copper	VQE-00-0961 VQE-07-013268 VQE-07-013459 VQE-99-0130
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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Lockheed Martin Systems Integration-Owego 1801 State Route 17C Owego, NY 13827, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 03640 Contact: Melita Nagerl Phone: 607-751-4665 Fax: 607-751-7714 EMail: melita.nagerl@lmco.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification:	MIL-PRF-31032/1, MIL-PRF-31032/2	VQE-00-0961 VQE-07-013459 VQE-99-0130
Panel Size:	24" X 30"	
Max./Min. Board Thickness:	.2"/Not Specified	
Max./Min. Base CU Thickness:	N/A	
Max./Min. Through Hole Size:	Not Specified/.018"	
Aspect Ratio:	8:1 (Through Hole)	
Max. Number of Layers:	16	
Min. Conductor Width:	.004"	
Min. Conductor Space:	.004"	
Part Mounting:	SMT, THM	
Rigid Base Material:	GI: Glass Base, Woven, Polyimide Resin, Heat Resistant	
Flex Base Material:	N/A	
Finish System:	Fused SnPb, HASL, NiAu	
Hole Preparation:	Permanganate Desmear, Plasma Etchback	
Alternate Construction:	N/A	
Copper Plating:	Electro-deposited Acid Copper	
Solder Resist:	LPI	
Controlled Impedance:	N/A	
Hole Fill/Via Plug:	N/A	
Flex Usage:	N/A	
Hole Wall Conductive Coating:	Electroless Copper	

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Lockheed Martin Systems Integration-Owego 1801 State Route 17C Owego, NY 13827, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 03640 Contact: Melita Nagerl Phone: 607-751-4665 Fax: 607-751-7714 EMail: melita.nagerl@lmco.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION **QUALIFICATION LETTERS:**

Specification:	MIL-PRF-31032/3, MIL-PRF-31032/4
Panel Size:	18" X 24"
Max./Min. Board Thickness:	.11"/Not Specified
Max./Min. Base CU Thickness:	N/A
Max./Min. Through Hole Size:	Not Specified/.016"
Aspect Ratio:	6:1 (Through Hole)
Max. Number of Layers:	18
Min. Conductor Width:	.003"
Min. Conductor Space:	.004"
Part Mounting:	SMT, THM
Rigid Base Material:	GF: Woven E-Glass, Epoxy Resin, Flame Resistant GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
Flex Base Material:	IC-4204/11 Adhesiveless IPC-4204/1 Acrylic Adhesiveless IPC-4204/2 IPC-4204/3 IPC-4204/4
Finish System:	Fused SnPb, HASL
Hole Preparation:	Permanganate Desmear, Plasma Etchback
Alternate Construction:	N/A
Copper Plating:	Electro-deposited Acid Copper
Solder Resist:	LPI
Controlled Impedance:	N/A
Hole Fill/Via Plug:	N/A
Flex Usage:	N/A
Hole Wall Conductive Coating:	Electroless Copper

VQE-00-0684
 VQE-07-013459

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Merix Corp. (Forest Grove, OR) 1521 Poplar Lane Forest Grove, OR 97116, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 01KV9 Contact: Roger Michalowski Phone: 781-639-5410 Fax: EMail: Customerservice@merix.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification: Panel Size: Max./Min. Board Thickness: Max./Min. Base CU Thickness: Max./Min. Through Hole Size: Aspect Ratio: Max. Number of Layers: Min. Conductor Width: Min. Conductor Space: Part Mounting: Rigid Base Material: Flex Base Material: Finish System: Hole Preparation: Alternate Construction: Copper Plating: Solder Resist: Controlled Impedance: Hole Fill/Via Plug: Flex Usage: Hole Wall Conductive Coating:	MIL-PRF-31032/1, MIL-PRF-31032/2 18" X 24" .13"/Not Specified N/A .003"/Not Specified (Laser Via) ".008" (Mechanical) 0.8:1 (Blind Vias) 10:1 (Through Hole) 26 .004" .004" MIX, SMT, THM GF: Woven E-Glass, Epoxy Resin, Flame Resistant N/A ENIG, HASL, Immersion Ag, Ni/Hard-Au Chemical Desmear Permanganate, Plasma Desmear, Etchback Blind Vias, Laser Drilled Vias Electrodeposited Acid Copper LPI Differential Methods ±5% at 50 ohms, Microstrip, Single Ended, Single Line N/A N/A N/A	VQ-09-017325

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Merix Corp. (San Jose, CA) 355 Turtle Creek Court San Jose, CA 95125-1316, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 0MHG5 Contact: Dave Williams Phone: 408-280-0422 Fax: 408-280-0641 E-Mail: david.williams@sj.merix.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification:	MIL-PRF-31032/1, MIL-PRF-31032/2	VQE-08-016481
		VQE-08-016632
Panel Size:	18" X 24"	
Max./Min. Board Thickness:	.13"/Not Specified	
Max./Min. Base CU Thickness:	N/A	
Max./Min. Through Hole Size:	.004"/.008" (laser drilled)	
	.25"/.008" (mechanical)	
Aspect Ratio:	0.8:1 (Blind Vias)	
	10:1 (Through Hole)	
Max. Number of Layers:	20	
Min. Conductor Width:	.004"	
Min. Conductor Space:	.004"	
Part Mounting:	MIX, SMT, THM	
Rigid Base Material:	GF: Woven E-Glass, Epoxy Resin, Flame Resistant	
	Gl: Glass Base, Woven, Polyimide Resin, Heat Resistant	
Flex Base Material:	N/A	
Finish System:	ENIG, HASL, Hard Gold, Nickel	
Hole Preparation:	Chemical Desmear, Desmear, Plasma Etchback	
Alternate Construction:	Blind Vias, Buried Vias, Sequential Lamination	
Copper Plating:	Electrodeposited Acid Copper	
Solder Resist:	LPI	
Controlled Impedance:	25-125 ohms +/-10%	
Hole Fill/Via Plug:	Non-conductive Filled Vias	
Flex Usage:	N/A	
Hole Wall Conductive Coating:	N/A	

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

<p>MANUFACTURER INFORMATION: Micom Corp. 475 Old Highway 8 NW New Brighton, MN 55112, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 34076 Contact: Larry Leonard Phone: 651-604-2639 Fax: 651-636-1352 EMail: lleonard@micomcircuits.com</p>
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification:	MIL-PRF-31032/1, MIL-PRF-31032/2	VQE-02-002780
Panel Size:	18" X 24"	VQE-03-2980
Max./Min. Board Thickness:	.239"/Not Specified	
Max./Min. Base CU Thickness:	N/A	
Max./Min. Through Hole Size:	Not Specified/.007"	
Aspect Ratio:	11:1 (Through Hole)	
Max. Number of Layers:	28	
Min. Conductor Width:	.004"	
Min. Conductor Space:	.004"	
Part Mounting:	SMT, THM	
Rigid Base Material:	GF: Woven E-Glass, Epoxy Resin, Flame Resistant GI: Glass Base, Woven, Polyimide Resin, Heat Resistant	
Flex Base Material:	N/A	
Finish System:	Fuse Following SnPb Plate, HASL	
Hole Preparation:	Permanganate Desmear/Etchback, Plasma Desmear/Etchback	
Alternate Construction:	Blind & Buried Vias	
Copper Plating:	Acid Copper	
Solder Resist:	Dry Film, LPI	
Controlled Impedance:	Characteristic $\pm 10\%$, Differential $\pm 10\%$	
Hole Fill/Via Plug:	N/A	
Flex Usage:	N/A	
Hole Wall Conductive Coating:	N/A	

**SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY**

MANUFACTURER INFORMATION: Philway Products, Inc. 701 Virginia Avenue Ashland, OH 44806, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 21971 Contact: Tom School Phone: 419-281-7777 Fax: 419-289-3447 E-Mail: quality@philway.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION	QUALIFICATION LETTERS:
Specification: MIL-PRF-31032/1 Panel Size: 18" X 21" Max./Min. Board Thickness: .09"/Not Specified Max./Min. Base CU Thickness: .002"/Not Specified Max./Min. Through Hole Size: .044"/.012" Aspect Ratio: 4:1 (Through Hole) Max. Number of Layers: 12 Min. Conductor Width: .005" Min. Conductor Space: .005" Part Mounting: MIX, SMT, THM Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant GI: Glass Base, Woven, Polyimide Resin, Heat Resistant GM: Glass Base, Woven, Triazine and/or Bismaleimide Modified Epoxy Resin, Flame Resistant Flex Base Material: N/A Finish System: HASL, IR Reflow following SnPb Plate Hole Preparation: Permanganate Desmear/Etchback Alternate Construction: N/A Copper Plating: Acid Copper Solder Resist: LPI Controlled Impedance: N/A Hole Fill/Via Plug: N/A Flex Usage: N/A Hole Wall Conductive Coating: N/A	VQE-99-1107

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

<p>MANUFACTURER INFORMATION: Pioneer Circuits, Inc. 3000 S. Shannon Street Santa Ana, CA 92704-6321, US</p>		<p>CAGE Code: 65723 Contact: Elias Gabriel Phone: 714-641-3132 x234 Fax: 714-641-3120 EMail:</p>
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION **QUALIFICATION LETTERS:**

Specification:	MIL-PRF-31032/1, MIL-PRF-31032/2
Panel Size:	18" X 24"
Max./Min. Board Thickness:	.177"/Not Specified
Max./Min. Base CU Thickness:	N/A
Max./Min. Through Hole Size:	.206"/.013"
Aspect Ratio:	11:1
Max. Number of Layers:	22
Min. Conductor Width:	.003"
Min. Conductor Space:	.003"
Part Mounting:	MIX, SMT, THM
Rigid Base Material:	G1: Glass Base, Woven, Polyimide Resin, Heat Resistant
Flex Base Material:	N/A
Finish System:	ENIG, Electrolytic Ni/Au Bondable, HASL, Reflowed Tin/Lead Fused, SMOBC, Selective Tin/Lead Strip
Hole Preparation:	Permanganate Desmear, Plasma Etchback
Alternate Construction:	Blind/Buried Vias, Filled Via Holes, Plated Sub-Assemblies, Sequential Lamination,
Copper Plating:	Acid Copper
Solder Resist:	Dry Film, LPI
Controlled Impedance:	Characteristic & Differential \pm 10%
Hole Fill/Via Plug:	N/A
Flex Usage:	N/A
Hole Wall Conductive Coating:	Electroless Copper

VQE-09-017323
VQE-09-017656

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

<p>MANUFACTURER INFORMATION: Pioneer Circuits, Inc. 3000 S. Shannon Street Santa Ana, CA 92704-6321, US</p>		<p>CAGE Code: 65723 Contact: Elias Gabriel Phone: 714-641-3132 x234 Fax: 714-641-3120 EMail:</p>
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION **QUALIFICATION LETTERS:**

Specification:	MIL-PRF-31032/3, MIL-PRF-31032/4
Panel Size:	24" X 36"
Max./Min. Board Thickness:	.185"/Not Specified
Max./Min. Base CU Thickness:	N/A
Max./Min. Through Hole Size:	.167"/.013"
Aspect Ratio:	11:1
Max. Number of Layers:	26
Min. Conductor Width:	.003"
Min. Conductor Space:	.003"
Part Mounting:	MIX, SMT, THM
Rigid Base Material:	GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
Flex Base Material:	Adhesiveless Polyimide
Finish System:	ENIG, Electrolytic Ni/Au Bondable, HASL, Reflowed Tin/Lead Fused, SMOBC, Selective Tin/Lead Strip
Hole Preparation:	Permanganate Desmear, Plasma Etchback
Alternate Construction:	Blind/Buried Vias, Bood Binder, Filled Via Holes, Plated Sub-Assemblies, Sequential Lamination
Copper Plating:	Acid Copper
Solder Resist:	LPI
Controlled Impedance:	Characteristic & Differential \pm 10%
Hole Fill/Via Plug:	N/A
Flex Usage:	Class A Flex During Installation, Class B Dynamic
Hole Wall Conductive Coating:	Electroless Copper

VQE-09-017323
VQE-09-017656

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

<p>MANUFACTURER INFORMATION: Pioneer Circuits, Inc. 3000 S. Shannon Street Santa Ana, CA 92704-6321, US</p>		<p>CAGE Code: 65723 Contact: Elias Gabriel Phone: 714-641-3132 x234 Fax: 714-641-3120 EMail:</p>
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION **QUALIFICATION LETTERS:**

Specification:	MIL-PRF-31032/1, MIL-PRF-31032/2
Panel Size:	18" X 24"
Max./Min. Board Thickness:	.275"/Not Specified
Max./Min. Base CU Thickness:	N/A
Max./Min. Through Hole Size:	.252"/.012"
Aspect Ratio:	11:1
Max. Number of Layers:	20
Min. Conductor Width:	.003"
Min. Conductor Space:	.003"
Part Mounting:	MIX, SMT, THM
Rigid Base Material:	GF: Woven E-Glass, Epoxy Resin, Flame Resistant
Flex Base Material:	N/A
Finish System:	ENIG, Electrolytic Ni/Au Bondable, HASL, Reflowed Tin/Lead Fused, SMOBC, Selective Tin/Lead Strip
Hole Preparation:	Permanganate Desmear, Plasma Etchback
Alternate Construction:	Blind/Buried Vias, Filled Via Holes, Plated Sub-Assemblies, Sequential Lamination
Copper Plating:	Acid Copper
Solder Resist:	Dry Film, LPI
Controlled Impedance:	Characteristic & Differential \pm 10%
Hole Fill/Via Plug:	N/A
Flex Usage:	N/A
Hole Wall Conductive Coating:	Electroless Copper

VQE-09-017323
VQE-09-017656

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

<p>MANUFACTURER INFORMATION: Pioneer Circuits, Inc. 3000 S. Shannon Street Santa Ana, CA 92704-6321, US</p>		<p>CAGE Code: 65723 Contact: Elias Gabriel Phone: 714-641-3132 x234 Fax: 714-641-3120 EMail:</p>
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION **QUALIFICATION LETTERS:**

Specification:	MIL-PRF-31032/3, MIL-PRF-31032/4
Panel Size:	18" X 24"
Max./Min. Board Thickness:	.1"/Not Specified
Max./Min. Base CU Thickness:	N/A
Max./Min. Through Hole Size:	.193"/.016"
Aspect Ratio:	6:1
Max. Number of Layers:	10
Min. Conductor Width:	.003"
Min. Conductor Space:	.003"
Part Mounting:	MIX, SMT, THM
Rigid Base Material:	G1: Glass Base, Woven, Polyimide Resin, Heat Resistant
Flex Base Material:	Adhesive Polyimide
Finish System:	ENIG, Electrolytic Ni/Au Bondable, HASL, Reflowed Tin/Lead Fused, SMOBC, Selective Tin/Lead Strip
Hole Preparation:	Permanganate Copper, Plasma Etchback
Alternate Construction:	Blind/Buried Vias, Filled Via Holes, Plated Sub-Assemblies, Sequential Lamination
Copper Plating:	Acid Copper
Solder Resist:	LPI
Controlled Impedance:	Characteristic & Differential \pm 10%
Hole Fill/Via Plug:	N/A
Flex Usage:	Class A Flex During Installation, Class B Dynamic
Hole Wall Conductive Coating:	Electroless Copper

VQE-09-017323
VQE-09-017656

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Printed Circuits, Inc. 1200 West 96th Street Bloomington, MN 55431, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 65114 Contact: Jim Smith Phone: 612-888-7900 Fax: 612-888-2719 EMail: jsmith@printedcircuits.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION	QUALIFICATION LETTERS:
Specification: MIL-PRF-31032/3, MIL-PRF-31032/4 Panel Size: 12" X 18", 18" X 24" Max./Min. Board Thickness: .12"/Not Specified Max./Min. Base CU Thickness: (1/2 oz.) Max./Min. Through Hole Size: Not Specified/.01" Aspect Ratio: 10:1 (Through Hole) Max. Number of Layers: 16 Min. Conductor Width: .004" Min. Conductor Space: .005" (+/- 10%) Part Mounting: MIX, SMT, THM Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant GI: Glass Base, Woven, Polyimide Resin, Heat Resistant Flex Base Material: IPC-4204/1 Acrylic Adhesive IPC-4204/11 Adhesiveless Finish System: Electroless Ni/Au, Electrolytic Ni/Au, Fused SnPb, HASL, SMOBC Hole Preparation: Plasma Desmear/Etchback Alternate Construction: N/A Copper Plating: Electrolytic Acid Copper Solder Resist: Dry Film, LPI, Controlled Impedance: N/A Hole Fill/Via Plug: N/A Flex Usage: Class A Flex to Install, Class B Continuous Flex Hole Wall Conductive Coating: Electroless Copper	VQE-01-0024

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Sanmina-SCI (San Jose) 2050 Bering Drive San Jose, CA 95131, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 3DR67 Contact: Darrell Myers Phone: 408-964-6515 Fax: 408-964-6453 E-Mail: darrell.myers@sanmina-sci.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification: MIL-PRF-31032/1, MIL-PRF-31032/2 Panel Size: 18" X 24" Max./Min. Board Thickness: .062"/Not Specified Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: .25"/.01" Aspect Ratio: 6:1 (Through Hole) Max. Number of Layers: 8 Min. Conductor Width: .003" Min. Conductor Space: .003" Part Mounting: SMT, THM Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant Flex Base Material: N/A Finish System: ENIG, HASL, ImmAg, OSP Hole Preparation: Plasma Desmear Alternate Construction: Foil Lamination Copper Plating: Acid Copper Solder Resist: Dry Film, LPI Controlled Impedance: 50-110 ohms ± 5% Hole Fill/Via Plug: N/A Flex Usage: N/A Hole Wall Conductive Coating: Electroless Copper	VQE-06-011137	

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification: MIL-PRF-31032/1, MIL-PRF-31032/2 Panel Size: 18" X 24" Max./Min. Board Thickness: .04"/Not Specified (for Plasma Etchback) .25"/Not Specified (for Plasma Desmear) Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: .25"/.008" Aspect Ratio: 15:1 (Through Hole) 1:2 (Microvias, Laser) Max. Number of Layers: 30 Min. Conductor Width: .003" Min. Conductor Space: .003" Part Mounting: MIX, SMT, THM Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant Flex Base Material: N/A Finish System: ENIG, Electrolytic Nickel Gold, HASL, Reflowed Solder Hole Preparation: Plasma Desmear//Etchback Alternate Construction: Foil Lamination, Min. Blind Via: 0.005" Laser, Min. Buried Via: 0.010" Mechanical Drill, Sequential Lamination Copper Plating: Electrolytic Acid Copper Solder Resist: Dry Film, LPI Controlled Impedance: 50-110 ohms ± 5% Hole Fill/Via Plug: Epoxy, Silver Flex Usage: N/A Hole Wall Conductive Coating: Electroless Copper	VQE-06-011137	

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Sovereign Circuits, Inc. 12080 DeBartolo Drive North Jackson, OH 44451, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 0GN71 Contact: Cynthia Savakis Phone: 330-538-3900, x211 Fax: 330-538-3820 E-Mail: quality@sovereign-circuits.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION **QUALIFICATION LETTERS:**

Specification:	MIL-PRF-31032/3, MIL-PRF-31032/4
Panel Size:	18" X 24"
Max./Min. Board Thickness:	.25"/Not Specified
Max./Min. Base CU Thickness:	.005"/Not Specified
Max./Min. Through Hole Size:	.008"/Not Specified
Aspect Ratio:	15:1 (Through Hole)
Max. Number of Layers:	24
Min. Conductor Width:	.003"
Min. Conductor Space:	.003"
Part Mounting:	MIX, Press Fit, SMT, THM
Rigid Base Material:	GF: Woven E-Glass, Epoxy Resin, Flame Resistant GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
Flex Base Material:	IPC-4204/1 Acrylic Adhesive IPC-4204/11 Adhesiveless
Finish System:	Fused SnPb, HASL, Immersion Ag, Immersion White tin, Ni/Au, OSP, Reflowed Pure Tin
Hole Preparation:	Permanganate Desmear/Etchback, Plasma Desmear/Etchback
Alternate Construction:	Blind Via, Buried Via, Cap Lamination, Foil Lamination
Copper Plating:	Electroless Acid Copper, Electroplated Acid Copper
Solder Resist:	Dry Film, LPI
Controlled Impedance:	Characteristic & Differential, 50, 75, 100 ohms ± 10%
Hole Fill/Via Plug:	Non-Conductive
Flex Usage:	N/A
Hole Wall Conductive Coating:	N/A

VQE-03-003121
 VQE-03-003214
 VQE-07-012925

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Sovereign Circuits, Inc. 12080 DeBartolo Drive North Jackson, OH 44451, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 0GN71 Contact: Cynthia Savakis Phone: 330-538-3900, x211 Fax: 330-538-3820 EMail: quality@sovereign-circuits.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION **QUALIFICATION LETTERS:**

Specification:	MIL-PRF-31032/1, MIL-PRF-31032/2
Panel Size:	18" X 24"
Max./Min. Board Thickness:	.25"/Not Specified
Max./Min. Base CU Thickness:	N/A
Max./Min. Through Hole Size:	.008"/Not Specified
Aspect Ratio:	15:1 (Through Hole)
Max. Number of Layers:	24
Min. Conductor Width:	.003"
Min. Conductor Space:	.003"
Part Mounting:	MIX, Press Fit, SMT, THM
Rigid Base Material:	BI: Aramid Fabric, Nonwoven, Polyimide Resin GF: Woven E-Glass, Epoxy Resin, Flame Resistant GI: Glass Base, Woven, Polyimide Resin, Heat Resistant
Flex Base Material:	N/A
Finish System:	Fused SnPb, HASL, Immersion Ag, Immersion White Tin, Ni/Au, Ni/Pd/Au, OSP, Reflowed Pure Tin
Hole Preparation:	Permanganate Desmear/Etchback, Plasma Desmear/Etchback
Alternate Construction:	Blind Vias, Buried Vias, Cap Lamination, Foil Lamination
Copper Plating:	Electroless Acid Copper, Electroplated Acid Copper
Solder Resist:	Dry Film, LPI
Controlled Impedance:	Characteristic, Differential, Dual Stripline, Embedded Microstrip, Microstrip, Range 30-150 ohms ±10%
Hole Fill/Via Plug:	Conductive, Non-conductive
Flex Usage:	N/A
Hole Wall Conductive Coating:	N/A

VQE-03-003121
 VQE-03-003214
 VQE-07-012925

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Speedy Circuits 5331 McFadden Avenue Huntington Beach, CA 92649-1204, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 66982 Contact: Jan Lesky Phone: 714-766-6243 Fax: 714-899-7074 EMail:
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION	QUALIFICATION LETTERS:
Specification: MIL-PRF-31032/6 Panel Size: 12" X 18" Max./Min. Board Thickness: .036"/Not Specified Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: .048"/.02" Aspect Ratio: 2:1 (Through Hole) Max. Number of Layers: 2 Min. Conductor Width: .005" Min. Conductor Space: .005" Part Mounting: SMT Rigid Base Material: GR: Glass Base, Nonwoven, Polytetrafluoroethylene Resin, Flame Resistant GY: Glass Base, Woven, Polytetrafluoroethylene Resin, Flame Resistant, for Microwave Application Flex Base Material: N/A Finish System: Electro-deposited fused SnPb Hole Preparation: N/A Alternate Construction: N/A Copper Plating: Acid Copper Solder Resist: N/A Controlled Impedance: N/A Hole Fill/Via Plug: N/A Flex Usage: N/A Hole Wall Conductive Coating: N/A	VQE-08-016434

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION	QUALIFICATION LETTERS:
Specification: N/A Panel Size: N/A Max./Min. Board Thickness: N/A Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: N/A Aspect Ratio: N/A Max. Number of Layers: N/A Min. Conductor Width: N/A Min. Conductor Space: N/A Part Mounting: N/A Rigid Base Material: N/A Flex Base Material: N/A Finish System: N/A Hole Preparation: N/A Alternate Construction: N/A Copper Plating: N/A Solder Resist: N/A Controlled Impedance: N/A Hole Fill/Via Plug: N/A Flex Usage: N/A Hole Wall Conductive Coating: N/A	N/A

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Speedy Circuits 5331 McFadden Avenue Huntington Beach, CA 92649-1204, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 66982 Contact: Jan Lesky Phone: 714-766-6243 Fax: 714-899-7074 E-Mail:
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification: MIL-PRF-31032/1, MIL-PRF-31032/2 Panel Size: 18" X 24" Max./Min. Board Thickness: .11"/Not Specified Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: .048"/.02" Aspect Ratio: 4:1 (Through Hole) Max. Number of Layers: 10 Min. Conductor Width: .005" Min. Conductor Space: .005" Part Mounting: SMT, THM Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant GI: Glass Base, Woven, Polyimide Resin, Heat Resistant Flex Base Material: N/A Finish System: Electro-deposited Fused SnPb, Electrolytic Hard Gold, Electrolytic Nickel, Electrolytic Soft Gold, HASL Hole Preparation: Etchback, Plasma Desmear Alternate Construction: Foil Lamination Copper Plating: Acid Copper Solder Resist: LPI Controlled Impedance: 100/50 ohms +/-10% Characteristic, 100/50 ohms +/-10% Differential Hole Fill/Via Plug: N/A Flex Usage: N/A Hole Wall Conductive Coating: Electroless Copper	VQE-08-016434	

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification: MIL-PRF-31032/3, MIL-PRF-31032/4 Panel Size: 18" X 24" Max./Min. Board Thickness: .11"/Not Specified Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: .048"/.02" Aspect Ratio: 4:1 (Through Hole) Max. Number of Layers: 10 Min. Conductor Width: .005" Min. Conductor Space: .005" Part Mounting: SMT, THM Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant Flex Base Material: Adhesiveless Polyimide Finish System: Electro-deposited Fused SnPb, Electrolytic Hard Gold, Electrolytic Nickel, Electrolytic Soft Gold, HASL Hole Preparation: Etchback, Plasma Desmear Alternate Construction: Foil Lamination Copper Plating: Electro-deposited Acid Copper Solder Resist: LPI Controlled Impedance: 100/50 ohms +/-10% Characteristic, 100/50 ohms +/-10% Differential Hole Fill/Via Plug: N/A Flex Usage: Class A Flex to Install, Class B Continuous Hole Wall Conductive Coating: Electroless Copper	VQE-08-016434	

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Speedy Circuits 5331 McFadden Avenue Huntington Beach, CA 92649-1204, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 66982 Contact: Jan Lesky Phone: 714-766-6243 Fax: 714-899-7074 E-Mail:
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION **QUALIFICATION LETTERS:**

Specification:	MIL-PRF-31032/5, MIL-PRF-31032/6
Panel Size:	12" X 18"
Max./Min. Board Thickness:	.068"/Not Specified .1"/Not Specified
Max./Min. Base CU Thickness:	N/A
Max./Min. Through Hole Size:	.048"/.02" .125"/.01"
Aspect Ratio:	10:1 2:1 (Through Hole) 6:1
Max. Number of Layers:	10
Min. Conductor Width:	.005"
Min. Conductor Space:	.005"
Part Mounting:	SMT, THM
Rigid Base Material:	Ceramic Filler - Homogenous GR: Glass Base, Nonwoven, Polytetrafluoroethylene Resin, Flame Resistant GY: Glass Base, Woven, Polytetrafluoroethylene Resin, Flame Resistant, for Microwave Application Hydrocarbon Resin Woven E-Glass
Flex Base Material:	N/A
Finish System:	Electro-deposited Fused SnPb, Electrolytic Hard and Soft Gold, Electrolytic Nickel, HASL, HASL
Hole Preparation:	Plasma Desmear
Alternate Construction:	N/A
Copper Plating:	Acid Copper
Solder Resist:	LPI
Controlled Impedance:	100/50 ohms +/-10% Characteristic, Differential, 50 ohms +/-10% Characteristic, Differential
Hole Fill/Via Plug:	N/A
Flex Usage:	N/A
Hole Wall Conductive Coating:	Electroless Copper, , ,

VQE-09-018657
VQE-09-018657

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

<p>MANUFACTURER INFORMATION: Strataflex Corp. 11 Dohme Avenue Toronto, Ontario, Canada M4B 1Y7</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 38661 Contact: Peter Pialis Phone: 416-752-2224 Fax: 416-752-6719 EMail: ppialis@strataflex.ca</p>
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION **QUALIFICATION LETTERS:**

<p>Specification: MIL-PRF-31032/3, MIL-PRF-31032/4</p> <p>Panel Size: 12" X 18"</p> <p>Max./Min. Board Thickness: .035"/Not Specified</p> <p>Max./Min. Base CU Thickness: N/A</p> <p>Max./Min. Through Hole Size: .011"/Not Specified</p> <p>Aspect Ratio: 3:1 (Through Hole)</p> <p>Max. Number of Layers: 7</p> <p>Min. Conductor Width: .007"</p> <p>Min. Conductor Space: .007"</p> <p>Part Mounting: SM, THM</p> <p>Rigid Base Material: N/A</p> <p>Flex Base Material: FR4 IPC-4101/21 Flexible Polyimide Clad IPC-4204/1 Flexible Polyimide Film IPC-4202/1 Flexible Polyimide Film/Acrylic IPC-4203/1 Woven E-Glass, Polyimide Resin IPC-4101/41</p> <p>Finish System: HASL</p> <p>Hole Preparation: Plasma Etchback</p> <p>Alternate Construction: N/A</p> <p>Copper Plating: Electrodeposited Acid Copper</p> <p>Solder Resist: N/A</p> <p>Controlled Impedance: N/A</p> <p>Hole Fill/Via Plug: N/A</p> <p>Flex Usage: N/A</p> <p>Hole Wall Conductive Coating: N/A</p>	<p>VQE-04-005354 VQE-08-015729</p>
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**SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY**

MANUFACTURER INFORMATION: Strataflex Corp. 11 Dohme Avenue Toronto, Ontario, Canada M4B 1Y7	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 38661 Contact: Peter Pialis Phone: 416-752-2224 Fax: 416-752-6719 EMail: ppialis@strataflex.ca
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION **QUALIFICATION LETTERS:**

Specification:	MIL-PRF-31032/3, MIL-PRF-31032/4
Panel Size:	12" X 18"
Max./Min. Board Thickness:	.035"/Not Specified
Max./Min. Base CU Thickness:	N/A
Max./Min. Through Hole Size:	.011"/Not Specified
Aspect Ratio:	3:1 (Through Hole)
Max. Number of Layers:	7
Min. Conductor Width:	.007"
Min. Conductor Space:	.007"
Part Mounting:	SMT, THM
Rigid Base Material:	FR4-IPC-4101/21 Flexible Polyimide Clad IPC-4204/1 Flexible Polyimide Film IPC-4202/1 Flexible Polyimide Film/Acylic IPC-4203/1
Flex Base Material:	N/A
Finish System:	HASL
Hole Preparation:	Plasma Desmear/Etchback
Alternate Construction:	N/A
Copper Plating:	Acid Copper
Solder Resist:	N/A
Controlled Impedance:	N/A
Hole Fill/Via Plug:	N/A
Flex Usage:	N/A
Hole Wall Conductive Coating:	N/A

VQE-04-5354

SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Strataflex Corp. 11 Dohme Avenue Toronto, Ontario, Canada M4B 1Y7	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 38661 Contact: Peter Pialis Phone: 416-752-2224 Fax: 416-752-6719 EMail: ppialis@strataflex.ca
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION **QUALIFICATION LETTERS:**

Specification:	MIL-PRF-31032/3, MIL-PRF-31032/4
Panel Size:	12" X 18"
Max./Min. Board Thickness:	.094"/Not Specified
Max./Min. Base CU Thickness:	N/A
Max./Min. Through Hole Size:	Not Specified/.008"
Aspect Ratio:	12:1 (Through Hole)
Max. Number of Layers:	12
Min. Conductor Width:	.006"
Min. Conductor Space:	.004"
Part Mounting:	N/A
Rigid Base Material:	N/A
Flex Base Material:	Flexible Polyimide Film/Acrylic IC-4203/1 Flexible Polyimide IPC-4204/11 Woven E-Glass, Polyimide Resin IPC-4101/40 Woven E-Glass, Polyimide Resin IPC-4101/41 Woven E-Glass, Polyimide Resin IPC-4101/42
Finish System:	HASL
Hole Preparation:	Plasma Etchback
Alternate Construction:	N/A
Copper Plating:	Electrodeposited Acid Copper
Solder Resist:	TA140 PSR-4000 HG
Controlled Impedance:	N/A
Hole Fill/Via Plug:	N/A
Flex Usage:	N/A
Hole Wall Conductive Coating:	Direct Metallization

VQE-04-005354
 VQE-08-015729

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Titan PCB East, Inc. 2 Industrial Way Amesbury, MA 01913, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 0BX48 Contact: Lance Arlander Phone: 978-388-5740 Fax: 978-388-5538 EMail: larlander@titaneast.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification:	MIL-PRF-31032/1, MIL-PRF-31032/2	VQE-04-6518
		VQE-05-7439
Panel Size:	18" X 24"	
Max./Min. Board Thickness:	.012"/Not Specified	
Max./Min. Base CU Thickness:	N/A	
Max./Min. Through Hole Size:	Not Specified/.012"	
Aspect Ratio:	10:1 (Through Hole)	
Max. Number of Layers:	14	
Min. Conductor Width:	.004"	
Min. Conductor Space:	.004"	
Part Mounting:	MIX, SMT, THM	
Rigid Base Material:	GF: Woven E-Glass, Epoxy Resin, Flame Resistant GI: Glass Base, Woven, Polyimide Resin, Heat Resistant	
Flex Base Material:	N/A	
Finish System:	ENIG, Electroplated Gold, HASL	
Hole Preparation:	Plasma Etchback	
Alternate Construction:	N/A	
Copper Plating:	Electrolytic Acid Copper	
Solder Resist:	Dry Film, LPI	
Controlled Impedance:	N/A	
Hole Fill/Via Plug:	N/A	
Flex Usage:	N/A	
Hole Wall Conductive Coating:	N/A	

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification:	MIL-PRF-31032/3, MIL-PRF-31032/4	VQE-04-6518
		VQE-05-7439
Panel Size:	18" X 24"	
Max./Min. Board Thickness:	.012"/Not Specified	
Max./Min. Base CU Thickness:	N/A	
Max./Min. Through Hole Size:	Not Specified/.012"	
Aspect Ratio:	10:1 (Through Hole)	
Max. Number of Layers:	14	
Min. Conductor Width:	.004"	
Min. Conductor Space:	.004"	
Part Mounting:	MIX, SMT, THM	
Rigid Base Material:	GF: Woven E-Glass, Epoxy Resin, Flame Resistant GI: Glass Base, Woven, Polyimide Resin, Heat Resistant	
Flex Base Material:	N/A	
Finish System:	ENIG, Electroplated Gold, HASL, Immersion Ni/Au	
Hole Preparation:	Plasma Etchback	
Alternate Construction:	N/A	
Copper Plating:	Electrodeposited Acid Copper	
Solder Resist:	Dry Film, LPI	
Controlled Impedance:	N/A	
Hole Fill/Via Plug:	N/A	
Flex Usage:	N/A	
Hole Wall Conductive Coating:	N/A	

**SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY**

MANUFACTURER INFORMATION: Titan PCB East, Inc. 2 Industrial Way Amesbury, MA 01913, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 0BX48 Contact: Lance Arlander Phone: 978-388-5740 Fax: 978-388-5538 EMail: larlander@titaneast.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION	QUALIFICATION LETTERS:
Specification: MIL-PRF-31032/3, MIL-PRF-31032/3 Panel Size: 12" X 18", 18" X 24" Max./Min. Board Thickness: .12"/Not Specified Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: N/A Aspect Ratio: N/A Max. Number of Layers: N/A Min. Conductor Width: N/A Min. Conductor Space: N/A Part Mounting: N/A Rigid Base Material: N/A Flex Base Material: N/A Finish System: N/A Hole Preparation: N/A Alternate Construction: N/A Copper Plating: N/A Solder Resist: N/A Controlled Impedance: N/A Hole Fill/Via Plug: N/A Flex Usage: N/A Hole Wall Conductive Coating: N/A	VQE-01-0024

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

<p>MANUFACTURER INFORMATION: TTM Technologies (Redmond) 17550 NE 67th Court Redmond, WA 98052-4939, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 3EDZ0 Contact: Margaret Schlosser Phone: 425-883-7575 Fax: EMail: mschlosser@ttmtech.com</p>
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification:	MIL-PRF-31032/1, MIL-PRF-31032/2	VQE-06-011027
Panel Size:	21.5" X 24.5"	VQE-06-011656
Max./Min. Board Thickness:	.063"/Not Specified (nominal)	
Max./Min. Base CU Thickness:	N/A	
Max./Min. Through Hole Size:	Not Specified/.01"	
Aspect Ratio:	6.3:1 (Through Hole)	
Max. Number of Layers:	12	
Min. Conductor Width:	.005"	
Min. Conductor Space:	.003"	
Part Mounting:	SMT, THM	
Rigid Base Material:	GF: Woven E-Glass, Epoxy Resin, Flame Resistant GI: Glass Base, Woven, Polyimide Resin, Heat Resistant	
Flex Base Material:	N/A	
Finish System:	ENIG	
Hole Preparation:	Desmear/Etchback	
Alternate Construction:	N/A	
Copper Plating:	Acid Copper	
Solder Resist:	N/A	
Controlled Impedance:	N/A	
Hole Fill/Via Plug:	N/A	
Flex Usage:	N/A	
Hole Wall Conductive Coating:	N/A	

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: TTM Technologies (Santa Ana) 2630 South Harbor Boulevard Santa Ana, CA 92704, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 1WQ42 Contact: Terry Lichte Phone: 714-241-0303, x3127 Fax: 714-241-0708 EMail: tlichte@ttmtech.comca
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification:	MIL-PRF-31032/1, MIL-PRF-31032/2	VQE-05-8644
		VQE-06-011211
Panel Size:	21" X 28"	
Max./Min. Board Thickness:	.2"/Not Specified	
Max./Min. Base CU Thickness:	N/A	
Max./Min. Through Hole Size:	.044"/.013"	
Aspect Ratio:	14:1 (Through Hole)	
Max. Number of Layers:	24	
Min. Conductor Width:	.003"	
Min. Conductor Space:	.003"	
Part Mounting:	SMT, THM	
Rigid Base Material:	GF: Woven E-Glass, Epoxy Resin, Flame Resistant	
Flex Base Material:	N/A	
Finish System:	ENIG, Fused SnPb, HASL, ImmAg, OSP	
Hole Preparation:	Desmear Etchback	
Alternate Construction:	Aspect Ratio Microvias: 1:1, Min. Blind Via: 0.005" Laser, Min. Buried Via: 0.0135" Mechanical Drill, Sequential Lamination	
Copper Plating:	Acid Copper	
Solder Resist:	Dry Film, LPI	
Controlled Impedance:	N/A	
Hole Fill/Via Plug:	N/A	
Flex Usage:	N/A	
Hole Wall Conductive Coating:	N/A	

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification:	MIL-PRF-31032/1, MIL-PRF-31032/2	VQE-05-8644
		VQE-06-011211
Panel Size:	18" X 24"	
Max./Min. Board Thickness:	.2"/Not Specified	
Max./Min. Base CU Thickness:	N/A	
Max./Min. Through Hole Size:	.044"/.013"	
Aspect Ratio:	14:1 (Through Hole)	
Max. Number of Layers:	24	
Min. Conductor Width:	.003"	
Min. Conductor Space:	.003"	
Part Mounting:	SMT, THM	
Rigid Base Material:	GI: Glass Base, Woven, Polyimide Resin, Heat Resistant	
Flex Base Material:	N/A	
Finish System:	ENIG, Fused SnPb, HASL, ImmAg, OSP	
Hole Preparation:	Desmear Etchback	
Alternate Construction:	Aspect Ratio Microvias: 1:1, Min. Blind Via: 0.005" Laser, Min. Buried Via: 0.0135" Mechanical Drill, Sequential Lamination	
Copper Plating:	Acid Copper	
Solder Resist:	Dry Film, LPI	
Controlled Impedance:	N/A	
Hole Fill/Via Plug:	N/A	
Flex Usage:	N/A	
Hole Wall Conductive Coating:	N/A	

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: TTM Technologies (Santa Clara) 400 Matthew Street Santa Clara, CA 95050, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 65916 Contact: Nellie Guitierrez Phone: 408-486-3184 Fax: 408-727-1003 EMail: nellie.guitierrez@ttmtech.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification:	MIL-PRF-31032/1, MIL-PRF-31032/2	VQE-03-3888
Panel Size:	18" X 24"	VQE-04-5823
Max./Min. Board Thickness:	.12"/Not Specified	
Max./Min. Base CU Thickness:	N/A	
Max./Min. Through Hole Size:	.191"/.012"	
Aspect Ratio:	9:1 (Through Hole)	
Max. Number of Layers:	20	
Min. Conductor Width:	.004"	
Min. Conductor Space:	.004"	
Part Mounting:	MIX, SMT, THM	
Rigid Base Material:	GF: Woven E-Glass, Epoxy Resin, Flame Resistant GI: Glass Base, Woven, Polyimide Resin, Heat Resistant	
Flex Base Material:	N/A	
Finish System:	HASL, Immersion Ni/Au	
Hole Preparation:	Plasma Desmear/Etchback	
Alternate Construction:	Blind Vias	
Copper Plating:	Electrolytic Acid Copper	
Solder Resist:	LPI, Screen Printed	
Controlled Impedance:	Characteristic, Differential +/-10%	
Hole Fill/Via Plug:	N/A	
Flex Usage:	N/A	
Hole Wall Conductive Coating:	Electroless Copper	

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification:	MIL-PRF-31032/3, MIL-PRF-31032/4	VQE-03-3895
Panel Size:	18" X 24"	
Max./Min. Board Thickness:	.12"/Not Specified	
Max./Min. Base CU Thickness:	N/A	
Max./Min. Through Hole Size:	.191"/.012"	
Aspect Ratio:	9:1 (Through Hole)	
Max. Number of Layers:	10	
Min. Conductor Width:	.004"	
Min. Conductor Space:	.004"	
Part Mounting:	MIX, SMT, THM	
Rigid Base Material:	GF: Woven E-Glass, Epoxy Resin, Flame Resistant GI: Glass Base, Woven, Polyimide Resin, Heat Resistant	
Flex Base Material:	IPC-4204/1 Acrylic Adhesive IPC-4204/11 Adhesiveless	
Finish System:	HASL, Immersion Ni/Au	
Hole Preparation:	Plasma Desmear/Etchback	
Alternate Construction:	N/A	
Copper Plating:	Acid Copper	
Solder Resist:	N/A	
Controlled Impedance:	N/A	
Hole Fill/Via Plug:	N/A	
Flex Usage:	Class A Flex to Install, Class B Continuous	
Hole Wall Conductive Coating:	Electroless Copper	

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

<p>MANUFACTURER INFORMATION: TTM Technologies (Santa Clara) 400 Matthew Street Santa Clara, CA 95050, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 65916 Contact: Nellie Guitierrez Phone: 408-486-3184 Fax: 408-727-1003 EMail: nellie.guitierrez@ttmtech.com</p>
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
<p>Specification: Panel Size: Max./Min. Board Thickness: Max./Min. Base CU Thickness: Max./Min. Through Hole Size: Aspect Ratio: Max. Number of Layers: Min. Conductor Width: Min. Conductor Space: Part Mounting: Rigid Base Material: Flex Base Material: Finish System: Hole Preparation: Alternate Construction: Copper Plating: Solder Resist: Controlled Impedance: Hole Fill/Via Plug: Flex Usage: Hole Wall Conductive Coating:</p>	<p>MIL-PRF-31032/Custom 18" X 24" .62"/.006" N/A .02"/.015" (drilled) .076"/.015" (drilled) 4:1 (Through Hole) 6 .007" .008" MIX, SMT, THM GF: Woven E-Glass, Epoxy Resin, Flame Resistant IPC-4103/10 Construction N/A ENIG Chemical Desmear Blind vias Electroless, Electrolytic Acid Copper LPI, SMOBC 50 ohms +/-10% N/A N/A N/A</p>	<p>VQE-07-13211</p>

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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: TTM Technologies (Stafford) 4 Old Monson Road P.O. Box 145, Stafford, TX 77497, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 5L706 Contact: Michelle Herbert Phone: 860-684-5881 Fax: 860-684-7425 E-Mail: michele.hebert@tycoelectronics.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION **QUALIFICATION LETTERS:**

Specification: MIL-PRF-31032/3, MIL-PRF-31032/4 Panel Size: 30" X 54" Max./Min. Board Thickness: .3"/.003" Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: .221"/.009" (drilled) Aspect Ratio: 9:1 (Through Hole) Max. Number of Layers: 28 Min. Conductor Width: .004" Min. Conductor Space: .004" Part Mounting: MIX, SMT, THM Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant GI: Glass Base, Woven, Polyimide Resin, Heat Resistant Flex Base Material: IPC-4204/1 Acrylic Adhesive IPC-4204/11 Adhesiveless Finish System: Bright Tin, Electroless Nickel/Immersion Gold, Electrolytic Hard & Soft Gold, Electrolytic Nickel, HASL, Immersion Tin, Reflowed Solder, SMOBC Hole Preparation: Plasma Etchback Alternate Construction: Blind and Buried Vias, Buried Resistors, Buried Via Aspect Ratio: 5:1, Copper Invar Copper, Micro Vias, Multiple Laminations Copper Plating: Acid Copper Solder Resist: Dy Film, Hole Fill, Hole Plug, LPI, Wet Mask Controlled Impedance: Characteristic, Differential, Dual Stripline, Embedded Microstrip, Microstrip, Range 30-150 ±10% Hole Fill/Via Plug: N/A Flex Usage: Class A Flex to Install, Class B Continuous Hole Wall Conductive Coating: Electroless Copper	VQE-03-3349
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SECTION I
LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: TTM Technologies (Stafford) 4 Old Monson Road P.O. Box 145, Stafford, TX 77497, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 5L706 Contact: Michelle Herbert Phone: 860-684-5881 Fax: 860-684-7425 EMail: michele.hebert@tycoelectroni cs.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION **QUALIFICATION LETTERS:**

Specification: MIL-PRF-31032/1, MIL-PRF-31032/2 Panel Size: 30" X 54" Max./Min. Board Thickness: 1.088"/Not Specified Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: .095"/.221" (drilled) Aspect Ratio: 10:1 (Through Hole) Max. Number of Layers: 68 Min. Conductor Width: .004" Min. Conductor Space: .004" Part Mounting: MIX, Press Fit, SMT, THM Rigid Base Material: AF: Aramid Fabric, Woven, Majority Polyfunctional Epoxy Resin BF: Aramid Fabric, Nonwoven, Epoxy Resin BI: Aramid Fabric, Nonwoven, Polyimide Resin GF: Woven E-Glass, Epoxy Resin, Flame Resistant GI: Glass Base, Woven, Polyimide Resin, Heat Resistant GM: Glass Base, Woven, Triazine and/or Bismaleimide Modified Epoxy Resin, Flame Resistant SC: Glass Base, Woven S-2, Fiber, Majority Cyanate Ester, Flame Resistant Flex Base Material: N/A Finish System: Bright Tin, Electroless Nickel/Immersion Gold, Electrolytic Hard & Soft Gold, Electrolytic Nickel, HASL, Immersion Tin, Reflowed Solder, SMOBC Hole Preparation: Plasma Etchback Alternate Construction: Blind and Buried Vias, Buried Resistors, Buried Via Aspect Ratio: 1:1, Copper Invar Copper, Micro Vias, Multiple Laminations Copper Plating: Acid Copper Solder Resist: Dry Film, Hole Fill, Hole Plug, LPI, Wet Mask Controlled Impedance: Characteristic, Differential, Dual Stripline, Embedded Microstrip, Microstrip, Range 30-150 ±10% Hole Fill/Via Plug: N/A Flex Usage: N/A Hole Wall Conductive Coating: Electroless Copper	VQE-03-3348
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LIST OF MANUFACTURERS' QUALIFIED CAPABILITIES FOR EACH TECHNOLOGY

MANUFACTURER INFORMATION: Unicircuit, Inc. 8192 Southpark Lane Littleton, CO 80120, US	PLANT LOCATION: Same Address as Manufacturer	CAGE Code: 66311 Contact: Bob Lageman Phone: 303-730-0505, x110 Fax: EMail: blageman@unicircuit.com
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CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification: MIL-PRF-31032/1, MIL-PRF-31032/2 Panel Size: 20" X 26" Max./Min. Board Thickness: .19"/Not Specified Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: .252"/.029" Aspect Ratio: 6.5:1 ((thru hole)) Max. Number of Layers: 24 Min. Conductor Width: .005" Min. Conductor Space: .005" Part Mounting: SMT, THM Rigid Base Material: GF: Woven E-Glass, Epoxy Resin, Flame Resistant Flex Base Material: N/A Finish System: HASL, Reflowed Tin Lead Hole Preparation: Plasma Etchback Alternate Construction: N/A Copper Plating: Electrodeposited Acid Copper Solder Resist: LPI Controlled Impedance: 100 ohms differential +/-10%, 53 ohms characteristic +/-7% Hole Fill/Via Plug: Conductive fill, Non-conductive fill Flex Usage: N/A Hole Wall Conductive Coating: Electroless Copper	VQE-09-17422	

CAPABILITIES BY TECHNOLOGY/ASSOCIATED SPECIFICATION		QUALIFICATION LETTERS:
Specification: MIL-PRF-31032/1, MIL-PRF-31032/2 Panel Size: 12" X 18" Max./Min. Board Thickness: .12"/Not Specified Max./Min. Base CU Thickness: N/A Max./Min. Through Hole Size: .129"/.02" Aspect Ratio: 6:1 (Through Hole) Max. Number of Layers: 16 Min. Conductor Width: .005" Min. Conductor Space: .005" Part Mounting: SMT, THM Rigid Base Material: GI: Glass Base, Woven, Polyimide Resin, Heat Resistant Flex Base Material: N/A Finish System: HASL, Reflowed Tin Lead Hole Preparation: Plasma Etchback Alternate Construction: Blind Via, Bured Via, Foil Lamination, Laser-drilled Microvias, Sequential Lamination Copper Plating: Electrodeposited Acid Copper, Electrodeposited Acid Copper Solder Resist: LPI Controlled Impedance: 100 ohms differential +/-10%, 53 ohms characteristic +/-7% Hole Fill/Via Plug: Conductive fill, Non-conductive fill Flex Usage: N/A Hole Wall Conductive Coating: Electroless Copper Laser Via Hole Size: .006 +/- .001	VQE-07-13789 VQE-09-17422	

SECTION II
LIST OF MANUFACTURERS BY ASSOCIATED SPECIFICATION

MIL-PRF-31032/1

Accurate Circuit Engineering

3019 S. Kilson Drive, Santa Ana, CA 92707, US

American Standard Circuits

RF Division, 475 Industrial Drive, West Chicago, IL 60185, US

Amphenol Printed Circuits

91 Northeastern Boulevard, Nashua, NH 03062, US

Calumet Electronics Corp.

25830 Depot Street, Calumet, MI 49913-1985, US

Cirexx International

791 Nuttman Street, Santa Clara, CA 95054,

Colonial Circuits, Inc.

1026 Warrenton Road, Fredericksburg, VA 22406-6200, US

Coretec Cleveland, Inc.

7 Ascot Parkway, Cuyahoga Falls, OH 44223, US

Coretec Denver, Inc.

10570 Bradford Road, Littleton, CO 80127, US

Coretec, Inc.

8150 Sheppard Avenue East, Scarborough, Ontario, Canada M1B 5K2

Cosmotronic, Inc.

16721 Noyes Avenue, Irvine, CA 92606, US

Diversified Systems

3939 West 56th Street, Indianapolis, IN 46254, US

Dynaco Corp.

1000 South Priest Drive, Tempe, AZ 85281-5238, US

Dynamic & Proto Circuits, Inc.

869 Barton Street, Stoney Creek, Ontario, Canada L8E 5G6

Dynamic Details, Inc.

1200 Severn Way, Dulles, VA 20166-8904, US

Dynamic Details, Inc., Anaheim

1220 N. Simon Circle, Anaheim, CA 92806, US

Electro Plate Circuitry

1430 Century Drive, Carrollton, TX 75006, US

Electrotek Corp.

7745 S. 10th Street, Oak Creek, WI 53154, US

Endicott Interconnect Technologies, Inc.

1701 North Street, P.O. Box 658, Endicott, NY 13760, US

Firan Technology Group

250 Finchdene Square, Scarborough, Ontario, Canada M1X 1A5

Global Innovation Corp.

901 Hensley Drive, Wylie, TX 75098, US

Hamby Corporation

27704 Avenue Scott, Valencia, CA 91355, US

Hans Brockstedt GmbH

Leiterplattenschnelldienst, Clara-Immerwahr-Str. 7, 24145, Kiel, Germany

Hughes Circuits

540 S. Pacific Street, San Marcos, CA 92078-4056, US

Lockheed Martin Systems Integration-Owego

1801 State Route 17C, Owego, NY 13827, US

Merix Corp. (Forest Grove, OR)

1521 Poplar Lane, Forest Grove, OR 97116, US

Merix Corp. (San Jose, CA)

355 Turtle Creek Court, San Jose, CA 95125-1316, US

Micom Corp.

475 Old Highway 8 NW, New Brighton, MN 55112, US

SECTION II
LIST OF MANUFACTURERS BY ASSOCIATED SPECIFICATION

MIL-PRF-31032/1

Philway Products, Inc.

701 Virginia Avenue, Ashland, OH 44806, US

Pioneer Circuits, Inc.

3000 S. Shannon Street, Santa Ana, CA 92704-6321, US

Sanmina-SCI (San Jose)

2050 Bering Drive, San Jose, CA 95131, US

Sovereign Circuits, Inc.

12080 DeBartolo Drive, North Jackson, OH 44451, US

Speedy Circuits

5331 McFadden Avenue, Huntington Beach, CA 92649-1204, US

Titan PCB East, Inc.

2 Industrial Way, Amesbury, MA 01913, US

TTM Technologies (Redmond)

17550 NE 67th Court, Redmond, WA 98052-4939, US

TTM Technologies (Santa Ana)

2630 South Harbor Boulevard, Santa Ana, CA 92704, US

TTM Technologies (Santa Clara)

400 Matthew Street, Santa Clara, CA 95050, US

TTM Technologies (Stafford)

4 Old Monson Road, P.O. Box 145, Stafford, TX 77497, US

Unicircuit, Inc.

8192 Southpark Lane, Littleton, CO 80120, US

SECTION II
LIST OF MANUFACTURERS BY ASSOCIATED SPECIFICATION

MIL-PRF-31032/2

Accurate Circuit Engineering

3019 S. Kilson Drive, Santa Ana, CA 92707, US

American Standard Circuits

RF Division, 475 Industrial Drive, West Chicago, IL 60185, US

Amphenol Printed Circuits

91 Northeastern Boulevard, Nashua, NH 03062, US

Calumet Electronics Corp.

25830 Depot Street, Calumet, MI 49913-1985, US

Cirexx International

791 Nuttman Street, Santa Clara, CA 95054,

Colonial Circuits, Inc.

1026 Warrenton Road, Fredericksburg, VA 22406-6200, US

Coretec Cleveland, Inc.

7 Ascot Parkway, Cuyahoga Falls, OH 44223, US

Coretec Denver, Inc.

10570 Bradford Road, Littleton, CO 80127, US

Coretec, Inc.

8150 Sheppard Avenue East, Scarborough, Ontario, Canada M1B 5K2

Cosmotronic, Inc.

16721 Noyes Avenue, Irvine, CA 92606, US

Diversified Systems

3939 West 56th Street, Indianapolis, IN 46254, US

Dynaco Corp.

1000 South Priest Drive, Tempe, AZ 85281-5238, US

Dynamic & Proto Circuits, Inc.

869 Barton Street, Stoney Creek, Ontario, Canada L8E 5G6

Dynamic Details, Inc.

1200 Severn Way, Dulles, VA 20166-8904, US

Dynamic Details, Inc., Anaheim

1220 N. Simon Circle, Anaheim, CA 92806, US

Electro Plate Circuitry

1430 Century Drive, Carrollton, TX 75006, US

Electrotek Corp.

7745 S. 10th Street, Oak Creek, WI 53154, US

Endicott Interconnect Technologies, Inc.

1701 North Street, P.O. Box 658, Endicott, NY 13760, US

Firan Technology Group

250 Finchdene Square, Scarborough, Ontario, Canada M1X 1A5

Global Innovation Corp.

901 Hensley Drive, Wylie, TX 75098, US

Hamby Corporation

27704 Avenue Scott, Valencia, CA 91355, US

Hans Brockstedt GmbH

Leiterplattenschnelldienst, Clara-Immerwahr-Str. 7, 24145, Kiel, Germany

Hughes Circuits

540 S. Pacific Street, San Marcos, CA 92078-4056, US

Lockheed Martin Systems Integration-Owego

1801 State Route 17C, Owego, NY 13827, US

Merix Corp. (Forest Grove, OR)

1521 Poplar Lane, Forest Grove, OR 97116, US

Merix Corp. (San Jose, CA)

355 Turtle Creek Court, San Jose, CA 95125-1316, US

Micom Corp.

475 Old Highway 8 NW, New Brighton, MN 55112, US

SECTION II
LIST OF MANUFACTURERS BY ASSOCIATED SPECIFICATION

MIL-PRF-31032/2

Pioneer Circuits, Inc.

3000 S. Shannon Street, Santa Ana, CA 92704-6321, US

Sanmina-SCI (San Jose)

2050 Bering Drive, San Jose, CA 95131, US

Sovereign Circuits, Inc.

12080 DeBartolo Drive, North Jackson, OH 44451, US

Speedy Circuits

5331 McFadden Avenue, Huntington Beach, CA 92649-1204, US

Titan PCB East, Inc.

2 Industrial Way, Amesbury, MA 01913, US

TTM Technologies (Redmond)

17550 NE 67th Court, Redmond, WA 98052-4939, US

TTM Technologies (Santa Ana)

2630 South Harbor Boulevard, Santa Ana, CA 92704, US

TTM Technologies (Santa Clara)

400 Matthew Street, Santa Clara, CA 95050, US

TTM Technologies (Stafford)

4 Old Monson Road, P.O. Box 145, Stafford, TX 77497, US

Unicircuit, Inc.

8192 Southpark Lane, Littleton, CO 80120, US

SECTION II
LIST OF MANUFACTURERS BY ASSOCIATED SPECIFICATION

MIL-PRF-31032/3

Calumet Electronics Corp.

25830 Depot Street, Calumet, MI 49913-1985, US

Cirexx International

791 Nuttman Street, Santa Clara, CA 95054,

Coretec Cleveland, Inc.

7 Ascot Parkway, Cuyahoga Falls, OH 44223, US

Cosmotronic, Inc.

16721 Noyes Avenue, Irvine, CA 92606, US

Dynaco Corp.

1000 South Priest Drive, Tempe, AZ 85281-5238, US

Hamby Corporation

27704 Avenue Scott, Valencia, CA 91355, US

Hans Brockstedt GmbH

Leiterplattenschnelldienst, Clara-Immerwahr-Str. 7, 24145, Kiel, Germany

Lockheed Martin Systems Integration-Owego

1801 State Route 17C, Owego, NY 13827, US

Pioneer Circuits, Inc.

3000 S. Shannon Street, Santa Ana, CA 92704-6321, US

Printed Circuits, Inc.

1200 West 96th Street, Bloomington, MN 55431, US

Sovereign Circuits, Inc.

12080 DeBartolo Drive, North Jackson, OH 44451, US

Speedy Circuits

5331 McFadden Avenue, Huntington Beach, CA 92649-1204, US

Strataflex Corp.

11 Dohme Avenue, Toronto, Ontario, Canada M4B 1Y7

Titan PCB East, Inc.

2 Industrial Way, Amesbury, MA 01913, US

TTM Technologies (Santa Clara)

400 Matthew Street, Santa Clara, CA 95050, US

TTM Technologies (Stafford)

4 Old Monson Road, P.O. Box 145, Stafford, TX 77497, US

SECTION II
LIST OF MANUFACTURERS BY ASSOCIATED SPECIFICATION

MIL-PRF-31032/4

Calumet Electronics Corp.

25830 Depot Street, Calumet, MI 49913-1985, US

Cirexx International

791 Nuttman Street, Santa Clara, CA 95054,

Colonial Circuits, Inc.

1026 Warrenton Road, Fredericksburg, VA 22406-6200, US

Coretec Cleveland, Inc.

7 Ascot Parkway, Cuyahoga Falls, OH 44223, US

Cosmotronic, Inc.

16721 Noyes Avenue, Irvine, CA 92606, US

Dynaco Corp.

1000 South Priest Drive, Tempe, AZ 85281-5238, US

Hamby Corporation

27704 Avenue Scott, Valencia, CA 91355, US

Hans Brockstedt GmbH

Leiterplattenschnelldienst, Clara-Immerwahr-Str. 7, 24145, Kiel, Germany

Lockheed Martin Systems Integration-Owego

1801 State Route 17C, Owego, NY 13827, US

Pioneer Circuits, Inc.

3000 S. Shannon Street, Santa Ana, CA 92704-6321, US

Printed Circuits, Inc.

1200 West 96th Street, Bloomington, MN 55431, US

Sovereign Circuits, Inc.

12080 DeBartolo Drive, North Jackson, OH 44451, US

Speedy Circuits

5331 McFadden Avenue, Huntington Beach, CA 92649-1204, US

Strataflex Corp.

11 Dohme Avenue, Toronto, Ontario, Canada M4B 1Y7

Titan PCB East, Inc.

2 Industrial Way, Amesbury, MA 01913, US

TTM Technologies (Santa Clara)

400 Matthew Street, Santa Clara, CA 95050, US

TTM Technologies (Stafford)

4 Old Monson Road, P.O. Box 145, Stafford, TX 77497, US

SECTION II
LIST OF MANUFACTURERS BY ASSOCIATED SPECIFICATION

MIL-PRF-31032/5

Speedy Circuits

5331 McFadden Avenue, Huntington Beach, CA 92649-1204, US

SECTION II
LIST OF MANUFACTURERS BY ASSOCIATED SPECIFICATION

MIL-PRF-31032/6

Global Innovation Corp.

901 Hensley Drive, Wylie, TX 75098, US

Speedy Circuits

5331 McFadden Avenue, Huntington Beach, CA 92649-1204, US

SECTION II
LIST OF MANUFACTURERS BY ASSOCIATED SPECIFICATION

MIL-PRF-31032/Custom

Colonial Circuits, Inc.

1026 Warrenton Road, Fredericksburg, VA 22406-6200, US

Cosmotronic, Inc.

16721 Noyes Avenue, Irvine, CA 92606, US

Endicott Interconnect Technologies, Inc.

1701 North Street, P.O. Box 658, Endicott, NY 13760, US

TTM Technologies (Santa Clara)

400 Matthew Street, Santa Clara, CA 95050, US

**SECTION III
ALPHABETICAL LIST OF QUALIFIED MANUFACTURERS**

<p>MANUFACTURER INFORMATION: Accurate Circuit Engineering 3019 S. Kilson Drive Santa Ana, CA 92707, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 0MNN9 Contact: James Hofer Phone: 714-546-162 Fax: 714-433-7418 EMail: James@ace-pcb.com</p>
<p>MANUFACTURER INFORMATION: American Standard Circuits RF Division, 475 Industrial Drive West Chicago, IL 60185, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 4AA34 Contact: Lori Ryan Phone: 603-639-5438 Fax: EMail: lori@asc-i.com</p>
<p>MANUFACTURER INFORMATION: Amphenol Printed Circuits 91 Northeastern Boulevard Nashua, NH 03062, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 57034 Contact: Denise Chevalier Phone: 603-879-3268 Fax: 603-879-2818 EMail: denise.chevalier@amphenol-tcs.com</p>
<p>MANUFACTURER INFORMATION: Calumet Electronics Corp. 25830 Depot Street Calumet, MI 49913-1985, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 65337 Contact: Robert Hall Phone: 906-337-1305 Fax: 906-337-5359 EMail: rhall@cec-up.com</p>
<p>MANUFACTURER INFORMATION: Cirexx International 791 Nuttman Street Santa Clara, CA 95054,</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 4MEG7 Contact: Don Angulo Phone: 408-988-3980 Fax: 408-988-4534 EMail: dangulo@cirexxintl.com</p>
<p>MANUFACTURER INFORMATION: Colonial Circuits, Inc. 1026 Warrenton Road Fredericksburg, VA 22406-6200, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 6T499 Contact: Mike Hill Phone: 540-753-5511, x125 Fax: 540-752-2109 EMail: quality@colonialcircuits.com</p>
<p>MANUFACTURER INFORMATION: Coretec Cleveland, Inc. 7 Ascot Parkway Cuyahoga Falls, OH 44223, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 7Z463 Contact: Mark Kasting Phone: 330-572-3400 Fax: 330-572-3434 EMail: mark_kasting/coretec@coretec-inc.com</p>
<p>MANUFACTURER INFORMATION: Coretec Denver, Inc. 10570 Bradford Road Littleton, CO 80127, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 75815 Contact: Douglas N. Berry Phone: 303-904-6119 Fax: 303-933-2934 EMail: dberry@coretec-denver.com</p>

SECTION III
ALPHABETICAL LIST OF QUALIFIED MANUFACTURERS

<p>MANUFACTURER INFORMATION: Coretec, Inc. 8150 Sheppard Avenue East Scarborough, Ontario, Canada M1B 5K2</p>	<p>PLANT LOCATIONS: 1. Same Address as Manufacturer 2. Coretec, Inc., CAGE Code: 3AF82, 2020 Ellesmere Road, Scarborough, Ontario, Canada M1H 2Z8</p>	<p>CAGE Code: 3AF82 Contact: Noor Al-Shaikh Phone: 416-208-2100 Fax: 416-439-1582 EMail: alshaikh@coretec-inc.com</p>
<p>MANUFACTURER INFORMATION: Cosmotronic, Inc. 16721 Noyes Avenue Irvine, CA 92606, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 63695 Contact: Alan Exley Phone: 949-660-0740 Fax: 949-553-8371 EMail: alan_exley@cosmotronic.com</p>
<p>MANUFACTURER INFORMATION: Diversified Systems 3939 West 56th Street Indianapolis, IN 46254, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 5S706 Contact: Linda Bell Phone: 317-299-9547, x238 Fax: 317-298-2061 EMail: linda.bell@divsys.com</p>
<p>MANUFACTURER INFORMATION: Dynaco Corp. 1000 South Priest Drive Tempe, AZ 85281-5238, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 61642 Contact: Ted Edwards Phone: 480-736-3728 Fax: 480-921-9830 EMail: tedwards@dynacocorp.com</p>
<p>MANUFACTURER INFORMATION: Dynamic & Proto Circuits, Inc. 869 Barton Street Stoney Creek, Ontario, Canada L8E 5G6</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 38898 Contact: Stephen Hazell Phone: 905-643-9900 Fax: 905-643-9911 EMail: stephenhazell@dapc.com</p>
<p>MANUFACTURER INFORMATION: Dynamic Details, Inc. 1200 Severn Way Dulles, VA 20166-8904, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 0K703 Contact: Tony Trnka Phone: 703-652-2266 Fax: 703-652-2271 EMail: atnka@va.ddiglobal.com</p>
<p>MANUFACTURER INFORMATION: Dynamic Details, Inc., Anaheim 1220 N. Simon Circle Anaheim, CA 92806, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 0BSG1 Contact: Rick Sylvain Phone: 714-688-7371 Fax: EMail: rsylvain@ddiglobal.com</p>
<p>MANUFACTURER INFORMATION: Electro Plate Circuitry 1430 Century Drive Carrollton, TX 75006, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 79616 Contact: James McNeal Phone: 972-466-0818 Fax: 972-466-9078 EMail: jimmm@eplate.com</p>

SECTION III
ALPHABETICAL LIST OF QUALIFIED MANUFACTURERS

<p>MANUFACTURER INFORMATION: Electrotek Corp. 7745 S. 10th Street Oak Creek, WI 53154, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 66030 Contact: Tom Tikusis Phone: 414-762-1390 Fax: 414-762-1510 EMail: sales@boards4u.com</p>
<p>MANUFACTURER INFORMATION: Endicott Interconnect Technologies, Inc. 1701 North Street P.O. Box 658, Endicott, NY 13760, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 3ECL3 Contact: Jose Rios Phone: 607-755-5896 Fax: 607-755-4649 EMail: JoseA.Rios@eitny.com</p>
<p>MANUFACTURER INFORMATION: Firan Technology Group 250 Finchdene Square Scarborough, Ontario, Canada M1X 1A5</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: L2665 Contact: Bryan Clark Phone: 416-299-4000 Fax: 416-292-4308 EMail: byanclark@firantechnology.com</p>
<p>MANUFACTURER INFORMATION: Global Innovation Corp. 901 Hensley Drive Wylie, TX 75098, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 04RV5 Contact: Bob Noland Phone: 214-291-1427 Fax: EMail: b noland@globalinnovationcorp.com</p>
<p>MANUFACTURER INFORMATION: Hamby Corporation 27704 Avenue Scott Valencia, CA 91355, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 07284 Contact: Sue Sharp Phone: 661-257-1924 Fax: 661-257-1213 EMail: suesharp@hambycorp.com</p>
<p>MANUFACTURER INFORMATION: Hans Brockstedt GmbH Leiterplattenschnelldienst, Clara-Immerwahr-Str. 7 24145, Kiel, Germany</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: C4831 Contact: Hilmar Klammer Phone: 0049-431-71966-0, -30 Fax: 0049-431-71966-29 EMail: klammer@brockstedt.de</p>
<p>MANUFACTURER INFORMATION: Hughes Circuits 540 S. Pacific Street San Marcos, CA 92078-4056, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 1KXU6 Contact: Joe Hughes Phone: 760-744-0300 Fax: 760-744-6388 EMail: joe@hughescircuits.com</p>
<p>MANUFACTURER INFORMATION: Lockheed Martin Systems Integration-Owego 1801 State Route 17C Owego, NY 13827, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 03640 Contact: Melita Nagerl Phone: 607-751-4665 Fax: 607-751-7714 EMail: melita.nagerl@lmco.com</p>

SECTION III
ALPHABETICAL LIST OF QUALIFIED MANUFACTURERS

<p>MANUFACTURER INFORMATION: Merix Corp. (Forest Grove, OR) 1521 Poplar Lane Forest Grove, OR 97116, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 01KV9 Contact: Roger Michalowski Phone: 781-639-5410 Fax: EMail: Customerservice@merix.com</p>
<p>MANUFACTURER INFORMATION: Merix Corp. (San Jose, CA) 355 Turtle Creek Court San Jose, CA 95125-1316, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 0MHG5 Contact: Dave Williams Phone: 408-280-0422 Fax: 408-280-0641 EMail: david.williams@sj.merix.com</p>
<p>MANUFACTURER INFORMATION: Micom Corp. 475 Old Highway 8 NW New Brighton, MN 55112, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 34076 Contact: Larry Leonard Phone: 651-604-2639 Fax: 651-636-1352 EMail: lleonard@micomcircuits.com</p>
<p>MANUFACTURER INFORMATION: Philway Products, Inc. 701 Virginia Avenue Ashland, OH 44806, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 21971 Contact: Tom School Phone: 419-281-7777 Fax: 419-289-3447 EMail: quality@philway.com</p>
<p>MANUFACTURER INFORMATION: Pioneer Circuits, Inc. 3000 S. Shannon Street Santa Ana, CA 92704-6321, US</p>		<p>CAGE Code: 65723 Contact: Elias Gabriel Phone: 714-641-3132 x234 Fax: 714-641-3120 EMail:</p>
<p>MANUFACTURER INFORMATION: Printed Circuits, Inc. 1200 West 96th Street Bloomington, MN 55431, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 65114 Contact: Jim Smith Phone: 612-888-7900 Fax: 612-888-2719 EMail: jsmith@printedcircuits.com</p>
<p>MANUFACTURER INFORMATION: Sanmina-SCI (San Jose) 2050 Bering Drive San Jose, CA 95131, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 3DR67 Contact: Darrell Myers Phone: 408-964-6515 Fax: 408-964-6453 EMail: darrell.myers@sanmina-sci.com</p>
<p>MANUFACTURER INFORMATION: Sovereign Circuits, Inc. 12080 DeBartolo Drive North Jackson, OH 44451, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 0GN71 Contact: Cynthia Savakis Phone: 330-538-3900, x211 Fax: 330-538-3820 EMail: quality@sovereign-circuits.com</p>

SECTION III
ALPHABETICAL LIST OF QUALIFIED MANUFACTURERS

<p>MANUFACTURER INFORMATION: Speedy Circuits 5331 McFadden Avenue Huntington Beach, CA 92649-1204, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 66982 Contact: Jan Lesky Phone: 714-766-6243 Fax: 714-899-7074 EMail:</p>
<p>MANUFACTURER INFORMATION: Strataflex Corp. 11 Dohme Avenue Toronto, Ontario, Canada M4B 1Y7</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 38661 Contact: Peter Pialis Phone: 416-752-2224 Fax: 416-752-6719 EMail: ppialis@strataflex.ca</p>
<p>MANUFACTURER INFORMATION: Titan PCB East, Inc. 2 Industrial Way Amesbury, MA 01913, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 0BX48 Contact: Lance Arlander Phone: 978-388-5740 Fax: 978-388-5538 EMail: larlander@titaneast.com</p>
<p>MANUFACTURER INFORMATION: TTM Technologies (Redmond) 17550 NE 67th Court Redmond, WA 98052-4939, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 3EDZ0 Contact: Margaret Schlosser Phone: 425-883-7575 Fax: EMail: mschlosser@ttmtech.com</p>
<p>MANUFACTURER INFORMATION: TTM Technologies (Santa Ana) 2630 South Harbor Boulevard Santa Ana, CA 92704, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 1WQ42 Contact: Terry Lichte Phone: 714-241-0303, x3127 Fax: 714-241-0708 EMail: tlichte@ttmtech.comca</p>
<p>MANUFACTURER INFORMATION: TTM Technologies (Santa Clara) 400 Matthew Street Santa Clara, CA 95050, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 65916 Contact: Nellie Guitierrez Phone: 408-486-3184 Fax: 408-727-1003 EMail: nellie.guitierrez@ttmtech.com</p>
<p>MANUFACTURER INFORMATION: TTM Technologies (Stafford) 4 Old Monson Road P.O. Box 145, Stafford, TX 77497, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 5L706 Contact: Michelle Herbert Phone: 860-684-5881 Fax: 860-684-7425 EMail: michele.hebert@tycoelectronics.com</p>
<p>MANUFACTURER INFORMATION: Unicircuit, Inc. 8192 Southpark Lane Littleton, CO 80120, US</p>	<p>PLANT LOCATION: Same Address as Manufacturer</p>	<p>CAGE Code: 66311 Contact: Bob Lageman Phone: 303-730-0505, x110 Fax: EMail: blageman@unicircuit.com</p>